

**ABSTRACT**

This technical user's guide describes the hardware architecture and configuration options of the J7200/DRA821 EVM.

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## 1 Introduction

The Jacinto7 J7200 (DRA821) EVM is a standalone test, development, and evaluation module system that enables developers to write software and develop hardware around Jacinto7 J7200 (DRA821) processor subsystem. The J7200 processor is a KeyStone™ III-based Multicore Arm® System-on-Chip (SoC).

The processor/device may be available in different configurations targeted for specific markets. This EVM will support development of the super-set device (J7200) as well as the market specific devices (DRA821). Many features of the J7200 system are available on the EVM, which gives developers the basic resources needed for most general-purpose type.

The J7200 EVM is comprised of :

- J7200 System On Module (SOM) board
- Jacinto7 Common Processor Board (CPB)
- Quad-Port Ethernet board (QPNNet)

J7200 EVM has been designed to enable customers to evaluate the Processor's performance with flexibility. For the flexibility, different interface/expansion boards have been designed. Some examples include:

- Gateway/Ethernet Switch/Industrial (GESI) Expansion Board

### 1.1 Key Features

The J7200 EVM is a high performance, standalone development platform that enables users to evaluate the Texas Instrument's Keystone III System-on-Chip (SoC).

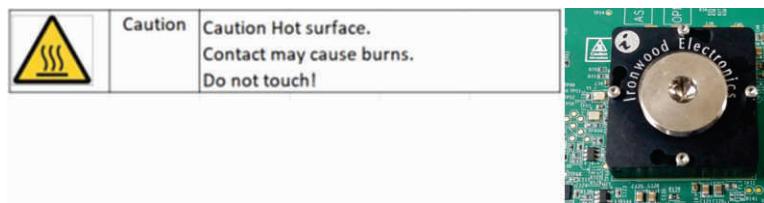
Below are the EVM's key features

- Processor:
  - J7200 (DRA821), 17.2mm x 17.2mm, 0.8mm pitch, 433-pin FCBGA
  - Support for corresponding socket
- Power Supply:
  - 12 V DC nominal input (6V-28V input range)
  - Optimized Power Management Solution for Processor
  - Integrated Power Measurement
- Memory:
  - DRAM, LPDDR4-3200, 4GByte total memory, support inline ECC
  - Octal-xSPI NOR flash, 512Mb memory (8bit)
  - HyperFlash + HyerRAM, 512Mb Flash memory + 256Mb RAM
  - Embedded Multi-Media Controller (eMMC) Flash memory, 16GB memory, v5.1 compliant
  - MicroSD Card Cage, UHS-I
  - Inter-integrated circuit (I2C) EEPROM, 1Mbit
- JTAG/Emulator:
  - Integrated XDS110 Emulator support
  - External emulator through 60-pin MIPI Connector
  - Trace Support through 60-pin MIPI Connector
  - Includes adapters for 14-pin and 20-pin CTI
- Supported Interfaces and Peripherals:
  - 4x CAN Interfaces, full CAN-FD support
  - 1x USB3.1 Type C Interface, support DFP, DRP, UFP modes
  - 4x USB2.0 Host Interfaces (2x for external cables)
  - 1x Audio Codec (PCM3168A), supports 2x Line Inputs, 4x Microphone Inputs, 2x Line
    - Outputs, 6x Headphone Outputs
  - 2-Lane PCIe Card Slot Gen3
  - Up to 4x Gbit Ethernet Ports, 1x Gbit Ethernet RGMII/DP83867 + 1x QSGMII/VSC8514
  - 5x universal asynchronous receiver/transmitter (UART) terminals via 2x USB FTDI (UART-over-USB)
  - 1x I3C headers
  - 1x ADC Header
- General Expansion Interface to support application specific add-on boards

- REACH and RoHS Compliant

## 1.2 Thermal Compliance

There is elevated heat on the processor/heatsink. **Use caution particularly at elevated ambient temperatures.** Although the processor/heatsink is not a burn hazard, caution should be used when handling the EVM due to increased heat in the area of the heatsink



**Figure 1-1. Thermal Caution**

## 1.3 REACH Compliance

In compliance with the Article 33 provision of the EU REACH regulation we are notifying you that this EVM includes component(s) containing at least one Substance of Very High Concern (SVHC) above 0.1%. These uses from Texas Instruments do not exceed 1 ton per year. The SVHC's are listed in [Table 1-1](#).

**Table 1-1. REACH Compliance**

Component Manufacturer	Component Type	Component Part Number	SVHC Substance	SVHC CAS (when available)
Tensility	Power Cable	10-02937	Lead	7439-92-1
Rosenberger	FPD Link Connector	D4S20G-400A5-C	Lead	7439-92-1
Littelfuse	Power fuse	0154010.DR	Lead	7439-92-1

## 1.4 Electrostatic Discharge (ESD) Compliance

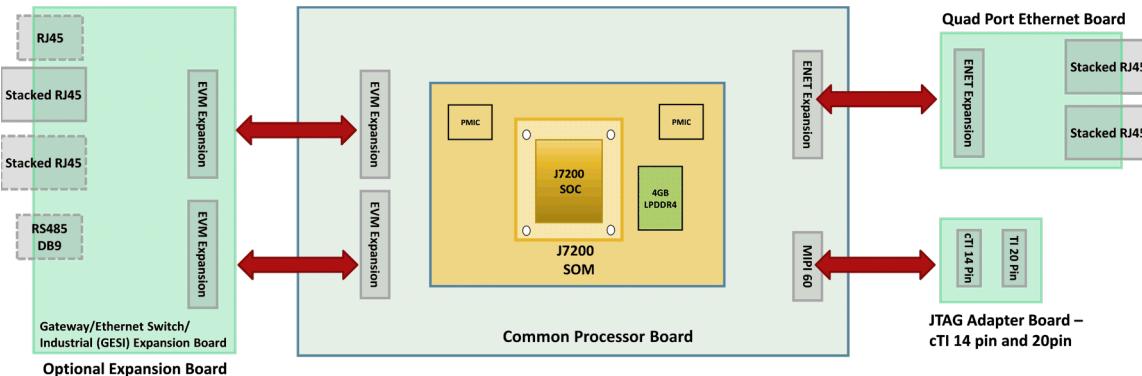
Components installed on the product are sensitive to Electrostatic Discharge (ESD). It is recommended this product be used in an ESD controlled environment. This may include a temperature and/or humidity controlled environment to limit the buildup of ESD. It is also recommended to use ESD protection such as wrist straps and ESD mats when interfacing with the product.

## 2 J7200 EVM Overview



**Figure 2-1. J7200 EVM Board**

Figure 2-2 shows an overall architecture of J7200 EVM.



**Figure 2-2. System Architecture Interface**

The J7200 EVM System on Module (SoM) board, a Jacinto7 Common Processor board and Quad-Port Ethernet Board. Detailed descriptions of these cards are explained in the following sections.

## 2.1 J7200 EVM Board Identification

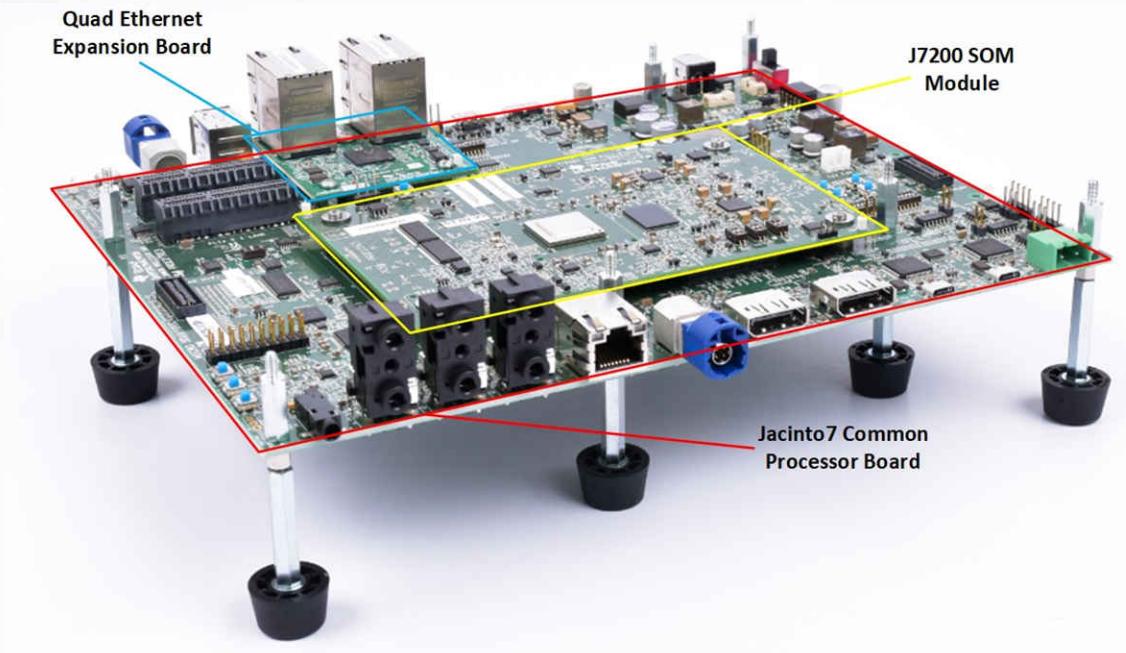


Figure 2-3. J7200 EVM Board Identification (SOM, CPB, QP Ethernet)

## 2.2 J7200 SOM Component Identification

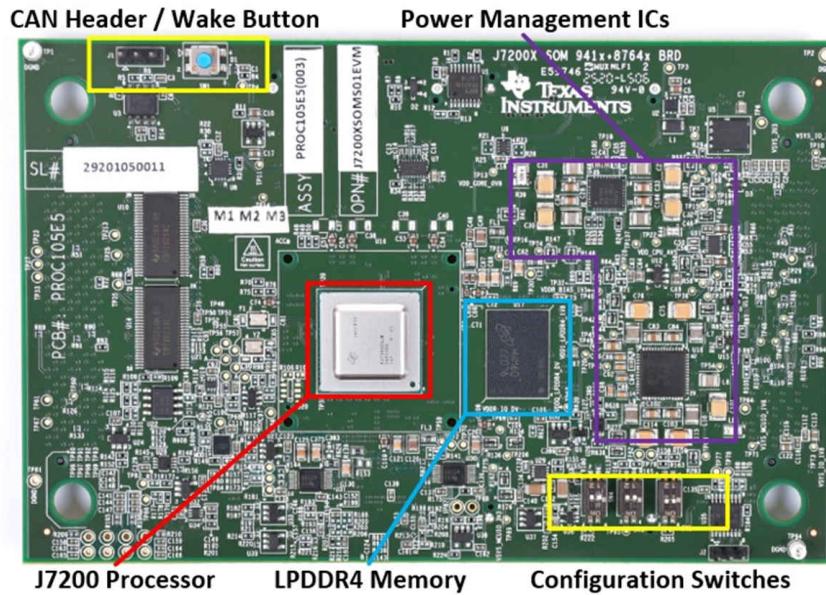


Figure 2-4. J7200 SOM Component Identification

## 2.3 Jacinto7 Common Processor Component Identification

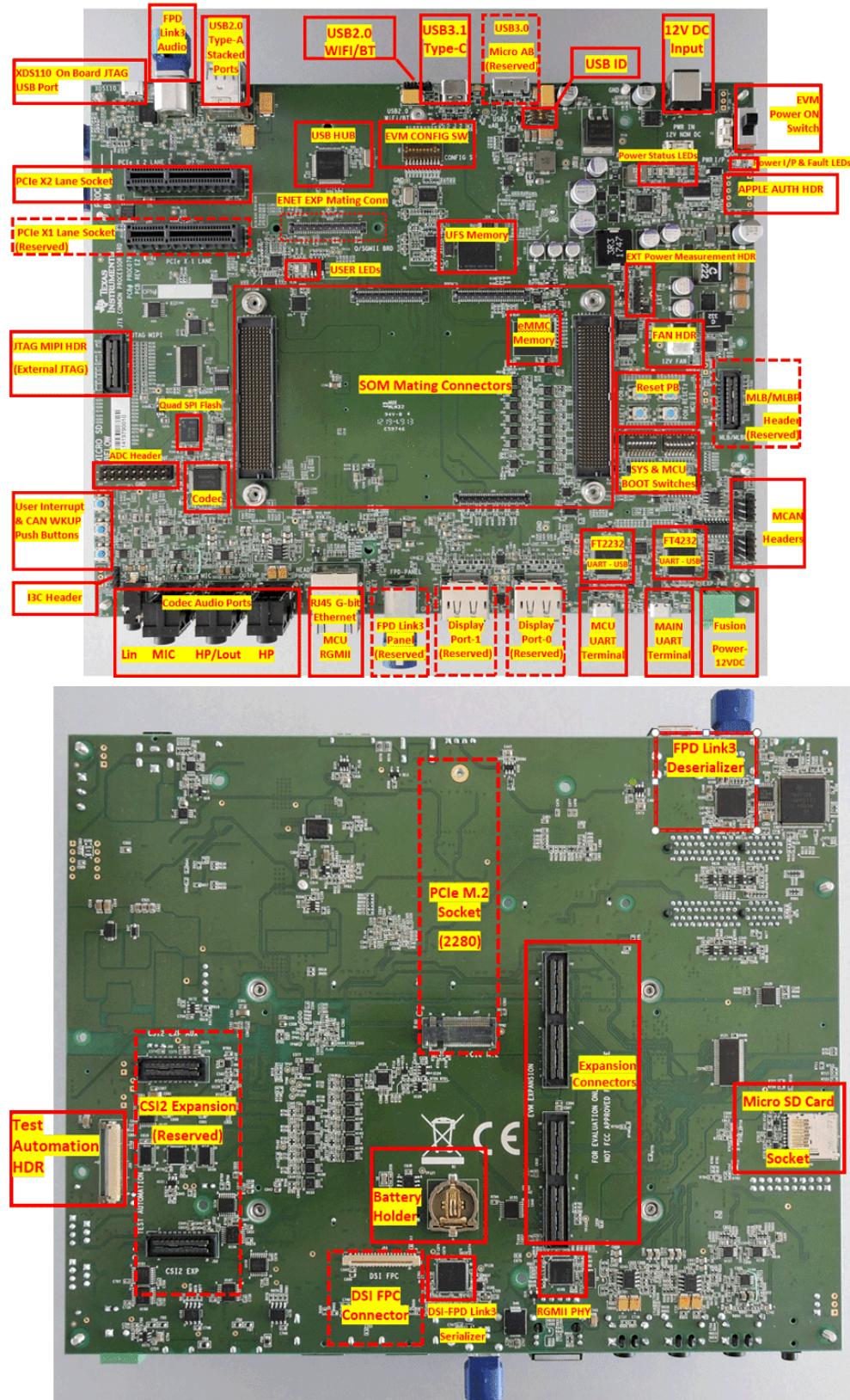
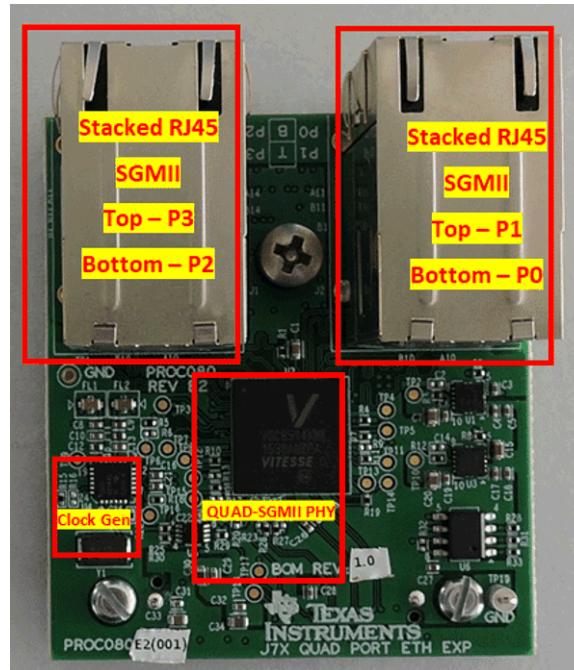


Figure 2-5. Jacinto7 Common Processor Component Identification

Because the Jacinto7 Common Processor board is used with different SOM boards featuring different Jacinto7 processors with different feature sets, some of the board's peripherals/interfaces may not be supported. For the J7200 SOM, the following interfaces are not supported:

- USB 3.0 uAB
- Display Port 0
- Display Port 1
- FPD deserializer
- PCIe M.2
- PCIe x1
- DSI interface
- UFS
- MLB
- CSI2

## 2.4 Quad Ethernet Components Identification



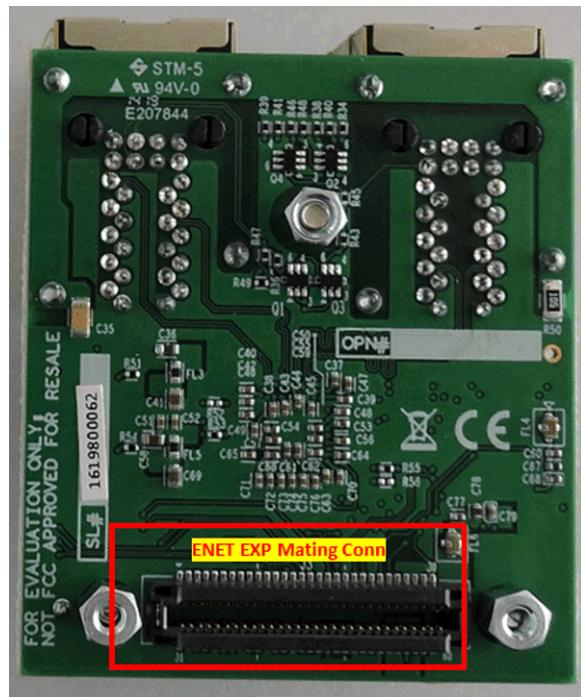


Figure 2-6. Quad Ethernet Component Identification

## 3 EVM User Setup/Configuration

### 3.1 Power Requirements

This EVM supports a wide input range of 6 V to 28 V. There is a DC Jack provided for power input:

An external power supply is required to power the EVM but is not included as part of the EVM kit. The external power supply requirements are:

Power Jack: 2.5 mm ID, 5.5 mm OD

Nom Voltage: 12 VDC, Recommended Minimum Current: 5000 mA

**Table 3-1. Recommended External Power Supply**

DigiKey Part#	Manufacturer	Manufacturer Part #
SDI65-12-U-P6-ND	CUI Inc.	SDI65-12-U-P6
SDI65-12-UD-P6-ND	CUI Inc.	SDI65-12-UD-P6

Note that the EVM's 2.5 x 5.5mm DC barrel jack connector (J7) supports 10A current rating. Polarity is outside barrel is Negative/GND, inside post is Positive/PWR.



**Figure 3-1. Connector Used for Power Input**

### 3.2 Power ON Switch and Power LEDs

The power to the EVM is controlled by the power ON/OFF switch (SW2) on the CPB. To turn the board ON, slide the switch in the direction as shown in [Figure 3-2](#).



**Figure 3-2. Power ON/OFF Switch**

#### 3.2.1 Over Voltage and Under Voltage Protection Circuit

The voltage protection circuit on the EVM protects the board from overvoltage, under voltage and transient voltage input cases. The safe operation input voltage range is 6 V to 28 V. A fault indication and power good LEDs are provided to indicate the power status.

**Table 3-2. Power LED Status**

LED	ON Status	OFF Status
LD2	Board Power on	Board Power off
LD3	Input voltage is >28 V or <6 V	Input voltage is within the limit



**Figure 3-3. Power ON/Fault LEDs**

### 3.2.2 Power Regulators and Power Status LEDs

The processor card utilizes an array of DC-DC converters to supply the various memories, clocks and other components on the Card with the necessary voltage and the power required.

The Dual Buck controller LM5140-Q1 provides the primary stage power conversion (12 V to 5 V/3.3 V). These 3.3 V and 5 V is the primary voltages for the SOM PMIC power resources.

The Buck-Boost controller LM5175 and another Buck controller LM5141 provides 12 V and 3.3 V supplies to the expansion connectors. The power good signals of these power regulators are used to generate the SoC PORz.

Multiple power-indication LEDs are provided on the card to give users positive confirmation of the status of output of major supplies. The LEDs indicated power in the various domains.

**Table 3-3. Power LEDs**

SI No	LED	Power Status	Sch Net Name
1	LD2	Input Power On/Off	VINPUT
2	LD7	Regulated Power On/Off	VSYS_3V3
3	LD5	SoC Main Domain On/Off	VSYS_IO_3V3
4	LD6	SoC MCU Domain On/Off	VSYS_MCUIO_3V3



**Figure 3-4. Power Status LEDs**

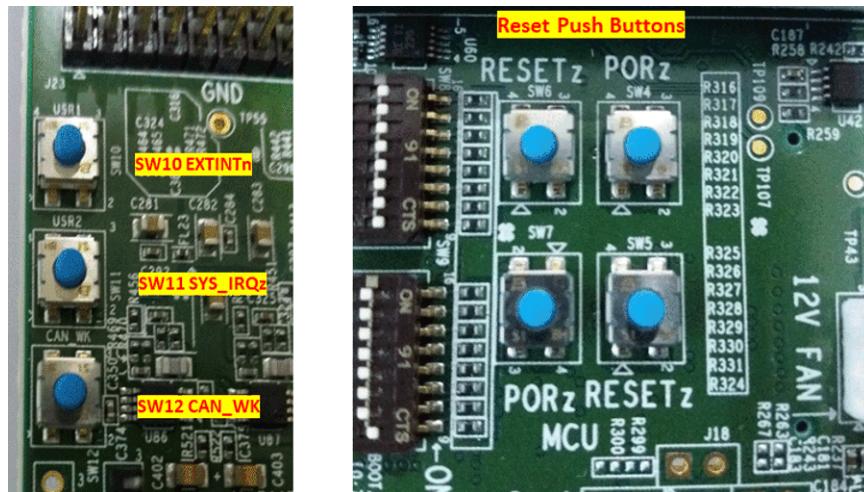
### 3.3 EVM Reset/Interrupt Push Buttons

The EVM supports multiple User Push buttons for providing Reset inputs and User Interrupts to the processor.

Table 3-4 lists the Push buttons that are placed on the Top side of the Common Processor Board.

**Table 3-4. EVM Push Buttons**

SI No.	Push Buttons	Signal	Function
1	SW7	MCU_PORz	MCU domain Power on Reset input
2	SW5	MCU_RESETz	MCU domain Warm Reset input
3	SW4	PORz	Main domain Power on Reset input
4	SW6	RESET_REQz	Main domain Warm Reset input
5	SW10	SOC_EXTINTn	External Interrupt input
6	SW11	SYS_IRQz	System IRQ Interrupt input
7	SW12	MCANO_WAKE	CAN Wakeup Input



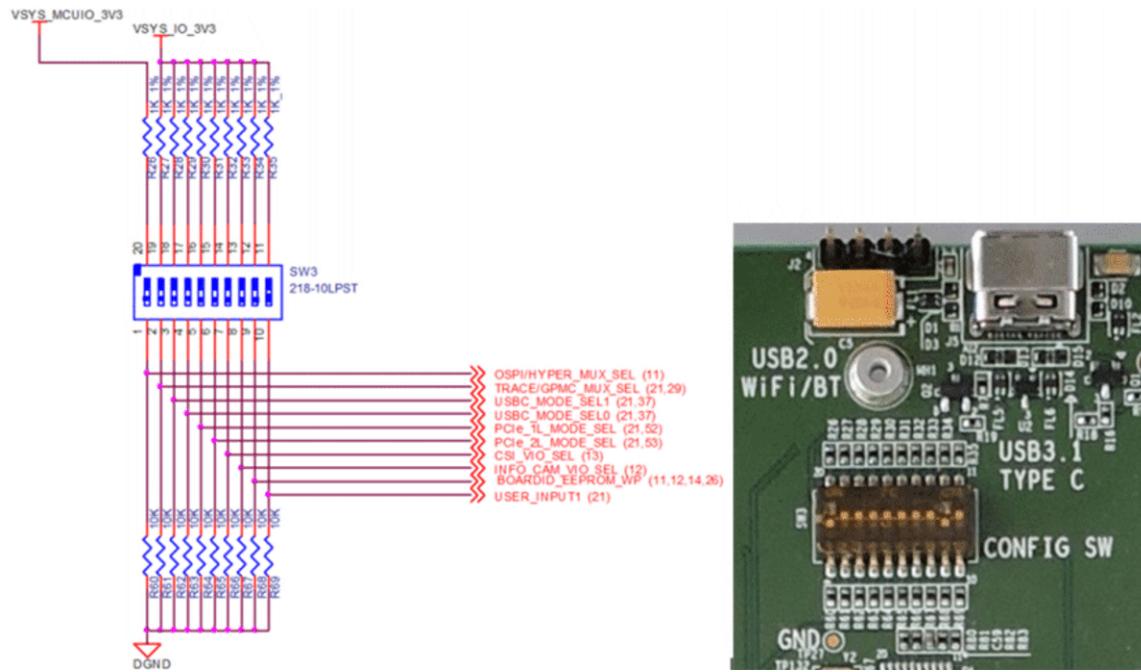
**Figure 3-5. EVM Push Buttons**

### 3.4 EVM DIP Switches

J7200 EVM supports User DIP Switches for EVM Configuration and SoC Boot mode set function.

#### 3.4.1 EVM Configuration DIP Switch

Figure 3-6 shows that the Common processor board has a dedicated EVM configuration switch (SW3) to set the various functions of EVM peripherals. Some of the configuration is for peripherals on the CPB, while other switches are used to configure peripherals on Expansion Boards. For those settings, the device-specific Expansion Board User's Guide will define the switch function.



**Figure 3-6. EVM Configuration DIP Switch**

**Table 3-5. EVM Configuration Switch Function**

Switch Name	Default Condition	Signal	Operation
SW3.1	OFF	OSPI/HYPER_MUX_SEL	MUX to select between non-volatile memories: '0' (OFF) = OSPI Memory connected to MCU_OSP10 Interface '1' (ON) = HyperFlash + HyperRAM connected to MCU_OSP10 Interface
SW3.2	ON	TRACE/GPMC_MUX_SEL	MUX to select Trace interface for debug: '0' (OFF) = Selected signals used for other peripherals (non-debug) '1' (ON) = Debug/Trace connected to MIPI-60 emulation interface
SW3.3	OFF	USBC_MODE_SEL1	Set Mode for USB Type C interface (USBO): '00' (OFF/OFF) = DFP (Downstream Facing Port)
SW3.4	OFF	USBC_MODE_SEL0	'01' (OFF/ON) = DRP (Dual Role Port) '1X' (ON, Don't Care) = UFP (Upstream Facing Port)
SW3.5	OFF	PCIe_1L_MODE_SEL	Not used with J7200 SOM
SW3.6	OFF	PCIe_2L_MODE_SEL	PCIe 2-Lane Mode Select (supports port PCIe1) '0' (OFF) = Root Complex '1' (ON) = End Point
SW3.7	ON	CSI_VIO_SEL	Not used with J7200 SOM
SW3.8	ON	INFO_CAM_VIO_SEL	Switch is to be used on Expansion board. See specific expansion board User's Guide for definition.

**Table 3-5. EVM Configuration Switch Function (continued)**

Switch Name	Default Condition	Signal	Operation
SW3.9	ON	BOARDID_EEPROM_WP	Sets EVM's configuration EEPROM Write Protection '0' (OFF) = Configuration EEPROM can be updated '1' (ON) = Configuration EEPROM cannot be updated/protected
SW3.10	ON	USER_INPUT1	User Define, maps to IO Expander Input '0' (OFF) = User Defined '1' (ON) = User Defined

### 3.4.2 SOM Configuration DIP Switch

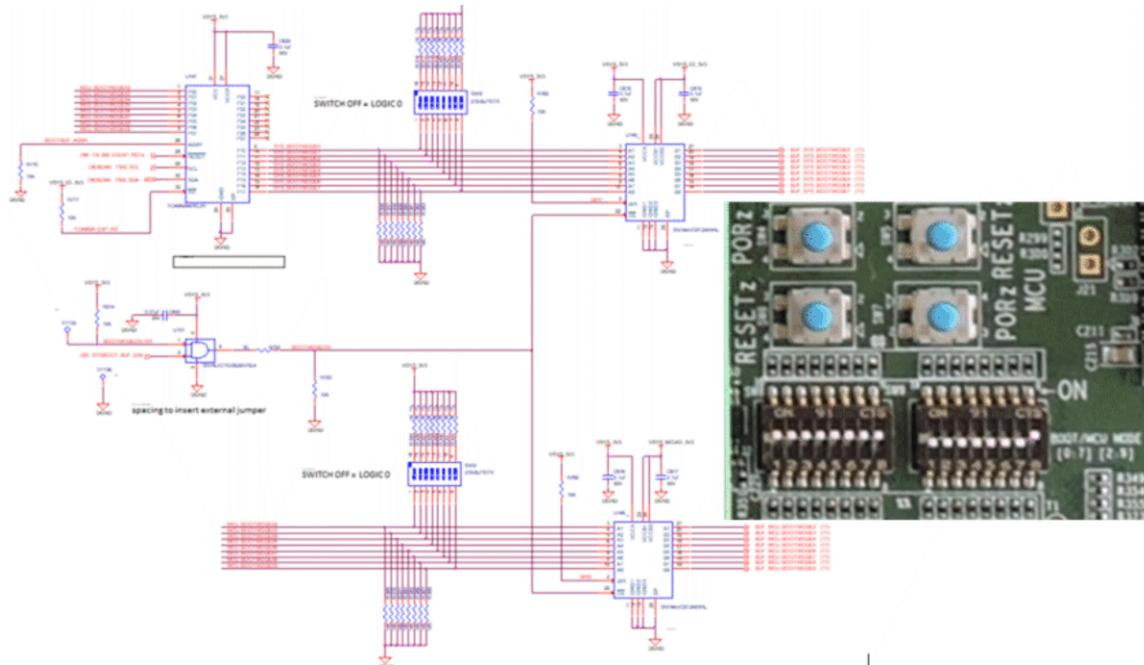
Table 3-6 shows the J7200 SOM configuration switches (SW1-SW4) to set the various functions SOM.

**Table 3-6. EVM Configuration Switch Function**

Switch Name	Default Condition	Signal	Operation
SW1	OFF	CANIO_RET_WAKE	Use as generic input (Push Button). Can be used as wake when system in IO retention mode
SW2.1	NA	NA	Not used
SW2.2	ON	LEOA_WDOG_DISABLE	Enable/Disable selection for PMIC Watchdog Timer: '0' (OFF) = PMIC watchdog timer is enabled '1' (ON) = PMIC watchdog timer is disabled (Default)
SW3.1	OFF	SOC_SAFETY_ERRz	Option to combine SOC_SAFETY_ERRz with MCU_SAFETY_ERR and PMIC. '0' (OFF) = SOC_SAFETY_ERRz (Main) is isolated from PMIC. (Default) '1' (ON) = SOC_SAFETY_ERRz (Main) is connected to PMIC.
SW3.2	OFF	SOC_PWR_EN	Manual method of enabling PMIC '0' (OFF) = PMIC enabled by EVM system (Default) '1' (ON) = PMIC enabled manually (test mode only)
SW4.1	OFF	VDDR_IO_DV_SRC_FB	Selects the I/O voltage level for LPDDR4: '0' (OFF) = Selects 1.1 V I/O for LPDDR4 (Default) '1' (ON) = Selects 0.6 V I/O for LPDDR4X (Not supported)
SW4.2	OFF	SEL_SOC_I2Cn	MUX to select I2C Interface for PMICs: '0' (OFF) = PMIC I2C to SoC WKUP I2C (Default) '1' (ON) = PMIC I2C to Ext header I2C (test mode only)

### 3.4.3 Boot Modes

The boot mode for the processor is determined by a bank of DIP switches (SW8, SW9). All of the boot mode pins have weak pull down resistors and a switch capable of connecting to a strong pull up resistor as shown in [Figure 3-7](#). Note that the OFF setting provides a low logic level ('0') and an ON setting provides a high logic level ('1').



**Figure 3-7. BOOT Switches Provided on the Processor Card**

[Table 3-7](#) and [Table 3-8](#) provide the switch map to the boot mode functions. For specific settings for each boot interface, see the *DRA821 Technical Reference Manual* (SPRUUIU2). The selectable boot interfaces supported on the EVM include: Octal-SPI, HyperFlash, SD-Card, eMMC, PCIe (as endpoint), CPSW, USB, UART, and EEPROM.

**Table 3-7. Wakeup Boot Mode Switch (SW9)**

Wakeup Boot Pin Map								
0:1 (Fixed to '00')	2 (SW9.1= OFF)	3	4 (SW9.3)	5 (SW9.4)	6 (SW9.5)	7 (SW9.6)	8 (SW9.7)	9 (SW9.8)
PLL Configuration (Fixed to 19.2 MHz)			Primary Boot Mode A		MCU Only	Rsvd	Rsvd (not for boot use)	

**Table 3-8. Main Boot Mode Switch (SW8)**

Main Boot Mode Pin Map							
0 (SW8.1)	1 (SW8.2)	2 (SW8.3)	(SW8.4)	4 (SW8.5)	5 (SW8.6)	6 (SW8.7)	7 (SW8.8)
Primary Boot Mode B	Backup Boot Mode				Primary Boot Mode Config		

Below are a few common examples for EVM boot mode configuration. For the latest settings, it is still recommended to refer to the TRM.

WKUP Bootmode	2	3	4	5	6	7	8	9
DIP SW9	(SW9.1)	(SW9.2)	(SW9.3)	(SW9.4)	(SW9.5)	(SW9.6)	(SW9.7)	(SW9.8)
SD Boot (Default)	OFF							
eMMC	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF
OSPI	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF
UART	OFF	ON	ON	ON	OFF	OFF	OFF	OFF
USB	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF
No Boot	OFF	ON	ON	ON	OFF	OFF	OFF	OFF

Main Bootmode	0	1	2	3	4	5	6	7
DIP SW8	(SW8.1)	(SW8.2)	(SW8.3)	(SW8.4)	(SW8.5)	(SW8.6)	(SW8.7)	(SW8.8)
SD Boot (Default)	ON	OFF	OFF	OFF	OFF	OFF	ON	OFF
eMMC	ON	OFF						
OSPI	OFF	OFF	OFF	OFF	OFF	ON	ON	OFF
UART	OFF							
USB	ON	OFF						
No Boot	ON	OFF	OFF	OFF	ON	OFF	OFF	OFF

### 3.4.4 Other Selection Switches

The USB2 port of is terminated with USB 3.0 Micro AB connector on the common processor board. The Host and Device function of SoC is set by the ID pin using DIP Switch SW1.

The ID and VBUS supply pin of USB connectors is connected to the DIP switch SW1 to configure the operational modes.

As previously mentioned, the USB port, USB3.0 microAB interface is not supported with the J7200 SoM.

### 3.5 EVM UART/COM Port Mapping

Three main domain UART ports of the SoC are interfaced with FT4232H for UART-to-USB functionality and terminated on a micro B connector (J44) provided on the CPB. When the EVM is connected to a Host using the provided USB cable, the computer can establish a Virtual Com Port which can be used with any terminal emulation application. The FT4232H is bus powered. Virtual Com Port drivers for the FT4232H can be obtained from <https://www.ftdichip.com/Products/ICs/FT4232H.htm>.

Out of Three UART ports, one UART port (UART0) is supports RS232 with Hardware flow control.

MCU and WKUP UART ports of the SoC are interfaced with FT2232H for UART-to-USB functionality and terminated on a micro B connector (J43) provided on the CPB. When the EVM is connected to a Host using the provided USB cable, the computer can establish a Virtual Com Port which can be used with any terminal emulation application. The FT2232H is bus powered. Virtual Com Port drivers for the FT4232H can be obtained from <https://www.ftdichip.com/Products/ICs/FT2232H.html>.

RS232 hardware control feature is supported on MCU UART0.

Both FT2232H and FT4232H circuits powered through USB VBUS. Since the circuits are powered through BUS power, the connection to the COM port will not be lost when the EVM power is removed. The maximum length of the IO cables should not exceed 3 meters.

**Table 3-9. UART Port Mapping**

UART Port	FTDI Bridge	USB Connector	COM Port	Remarks
MAIN_UART0	FT4232H	J44	COM 1	Supports Hardware Flow control
MAIN_UART1			COM 2	
MAIN_UART3			COM 3	
NA			COM 4	NA
MCU_UART0	FT2232H	J43	COM 5	Supports Hardware Flow control
WKUP_UART0			COM 6	

The EEPROM of FTDI bridges are programmed with the CPB serial number, which makes it easier for users to identify the connected COM port with the board serial number when one or more boards connected to the computer.

Example Programming content:

FT4232H (Main)

CPB Serial number: 14197900028

Programmed Serial number on FT4232H EEPROM: 141979000280A

FT2232H (MCU and WKUP)

CPB Serial number: 14197900028

Programmed Serial number on FT4232H EEPROM: 141979000280B

## 4 J7200 EVM Hardware Architecture

This section explains the Hardware Architecture of J7200 EVM in detail.

### 4.1 J7200 EVM Hardware Top Level Diagram

Figure 4-1 shows the functional block diagram of the J7200 EVM.

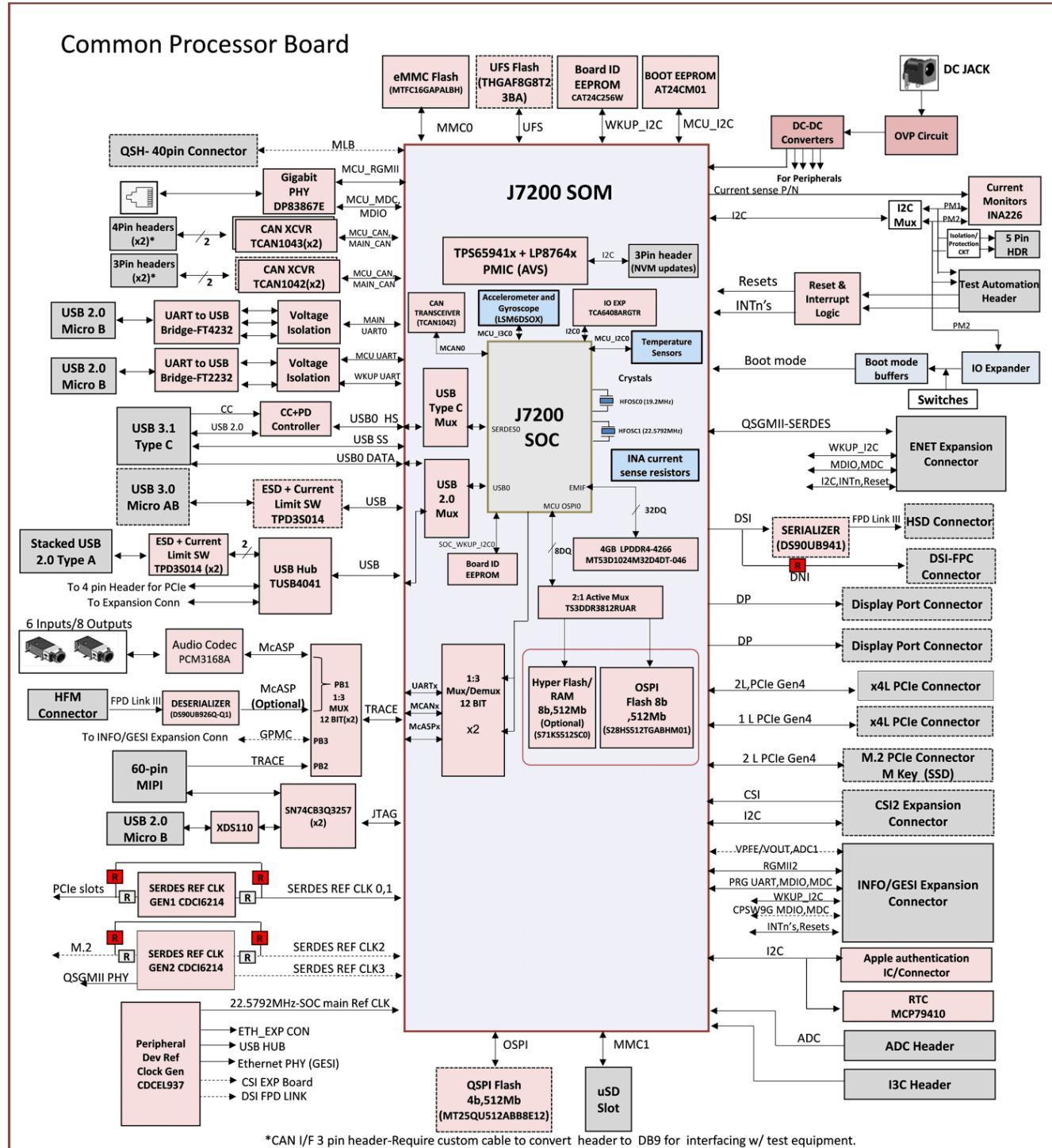


Figure 4-1. J7200 EVM Functional Block Diagram

Figure 4-2 shows the Quad Port Ethernet Expansion Board functional block diagram.

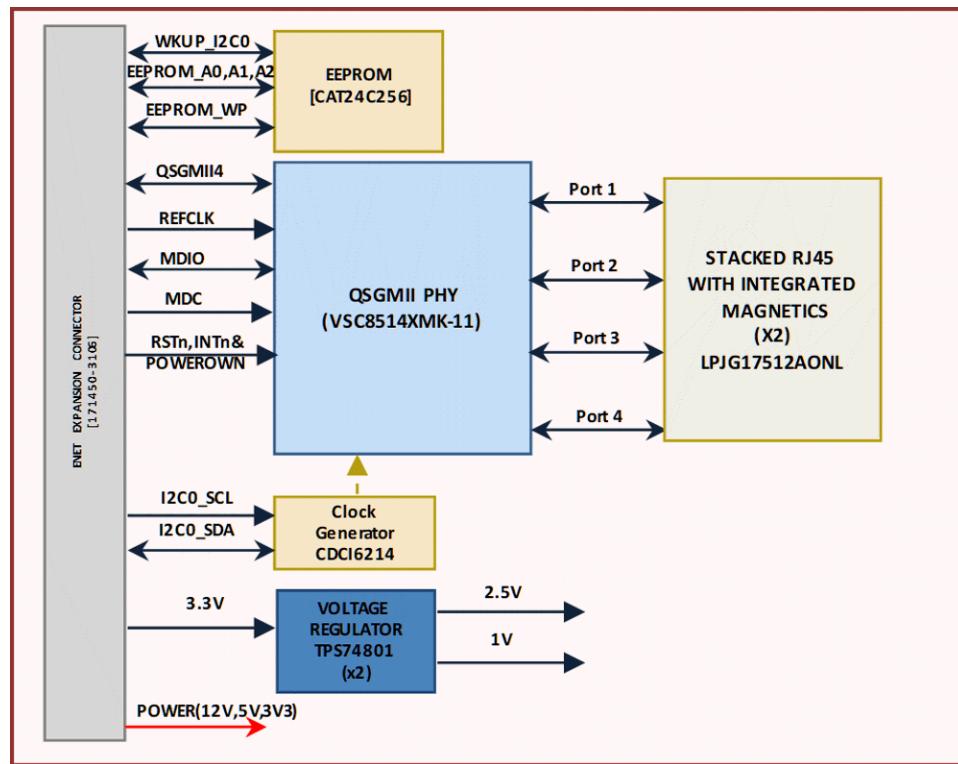


Figure 4-2. Quad Port Ethernet Expansion Functional Block Diagram

## 4.2 J7200 EVM Interface Mapping

J7200 EVM Interface Mapping table is provided in [Table 4-1](#).

Table 4-1. J7200 EVM Interface Mapping Table

Interface Name	Port on SoC	Connected Peripheral
Memory – LPDDR4	DDR0	LPDDR4 Memory (MT53D1024M32D4DT)
Memory – OSPI	MCU_OSPI0	xSPI Memory (S28HS512TGABHM010) (Channel B of 1:2 Mux TS3DDR3812RUAR)
Memory – Hyper Flash	MCU_OSPI0	'Hyper flash Memory (S71KS512SC0BHV000) (Channel C of 1:2 Mux TS3DDR3812RUAR)
Memory – eMMC	MMC0	eMMC Memory (MTFC16GAPALBH-AAT ES)
Memory – Micro SD Socket	MMC1	Micro-SD Card Cage (DM3BT-DSF-PEJS)
Memory – Board ID EEPROM	WKUP_I2C0	EEPROM Memory (CAT24C256WI-GT3) (CAV24C256WE-GT3 for J700 SOM)
Memory – Boot EEPROM	MCU_I2C0	EEPROM Memory (AT24CM01)
Ethernet – RGMII	MCU_RGMII1	Ethernet PHY (DP83867ERGZT)
Ethernet – Quad SGMII	SERDES0 (SGMII1)	Ethernet PHY (VSC8514XMK)
USB – 3.1 Type C + PD + CC Controller	SERDES0 (USB0)	USB PD + CC Controller (PTPS25830QWRHBTQ1 + TUSB321RWBR) (Type C Superspeed lines are muxed using 1:2 mux HD3SS3212IRKSR)
USB – 2.0 (HUB)	USB0	USB 2.0 Hub (TUSB4041PAPR) (USB0 lines of SoC are muxed between HUB and Type C using two mux ICs TS3USB221ARSER and SN74CB3Q3257PWR)
Audio Codec	McASP0	Audio Codec (PCM3168APAP)
PCI2 – x4 Lane Socket (x2 Lane)	SERDES1 (PCIe1)	PCIe 4-L Connector (10142333-10111MLF)

**Table 4-1. J7200 EVM Interface Mapping Table (continued)**

Interface Name	Port on SoC	Connected Peripheral
UART Terminal (UART-to-USB)	UART [0:1] and 3	Quad Port USB-UART bridge (FT4232HL)
UART Terminal (UART-to-USB)	WKUP_UART0 and MCU_UART0	Dual Port USB-UART bridge (FT2232HL)
CAN (4x)	MCU_MCAN0	CAN Transceiver W/ Wake function (TCAN1043-Q1)
	MCU_MCAN1	CAN Transceiver TCAN1042HGVD
	MCAN3	CAN Transceiver W/ Wake function (TCAN1043-Q1) (1:3 active mux is used on SoM board)
	MCAN0	CAN Transceiver (TCAN1042HGVD)
ADC Header	MCU_ADC0	2x10, 2.54mm Header (TSW-110-07-S-D)

### 4.3 I2C Address Mapping

Table 4-2 shows the complete I2C address mapping details on the EVM.

**Table 4-2. J7200 EVM I2C Table**

Board	I2C Port	Device/Function	Part#	I2C Address
EVM/SoM	WKUP_I2C0	Board ID EEPROM	CAV24C256WE-GT3	0x50
EVM/CPB	WKUP_I2C0	Board ID EEPROM	CAT24C256W	0x51
EXP/QSGMII	WKUP_I2C0	Board ID EEPROM	CAT24C256W	0x54
EVM/SoM	WKUP_I2C0	PMICs	PMIC A: TPS659414F4RWERQ1 PMIC B: LP876441A1RQKRQ1	PMIC A: 0x48, 0x49, 0x4A & 0x4B PMIC B: 0x4C, 0x4D, 0x4E & 0x4F
EVM/SoM	MCU_I2C0	Temperature Sensors	TMP100NA/3K	0x48, 0x49
EVM/CPB	MCU_I2C0	Boot EEPROM	AT24CM01	0x50, 0x51
EVM/CPB	SoC_I2C0	8 bit I2C GPIO Expander	TCA6408ARGTR	0x21
EVM/CPB	SoC_I2C0	SerDes Clock gen #2	CDCI6214	0x77,0x76
EVM/CPB	SoC_I2C0	Peripheral Clock Gen	CDCEL937-Q1	0x6D
EVM/CPB	SoC_I2C0	16bit I2C GPIO EXPANDER1	TCA6416ARTWR	0x20
EVM/CPB	SoC_I2C0	24bit I2C GPIO EXPANDER2	TCA6424ARGJR	0x22
EVM/CPB	SoC_I2C0	RTC 7'b	MCP79410	0x57, 0x6F
EVM/CPB	SoC_I2C0	I2C MUX for both x2LANE and x1LANE PCIe Interface	TCA9543APWR	0x70
EVM/CPB	SoC_I2C0	QSGMII PHY Ref Clock Generator (QPENET Board)	CDCI6214	0x77
EVM/CPB	SoC_I2C2	Current Monitors 1(PM1_I2C)	INA226	0x40-0x4F
EVM/CPB	SoC_I2C2	Current Monitors 2(PM2_I2C)	INA226	0x40-0x4F
EVM/CPB	SoC_I2C2	Test Automation Header	<connector interface>	
EVM/CPB	SoC_I2C1	8 bit I2C GPIO Expander-3	TCA6408ARGTR	0x20
EVM/CPB	SoC_I2C1	Audio Codec – 1	PCM3168A-Q1	0x44
EVM/CPB	SoC_I2C1	FPD Link-III De-serializer (McASP)	DS90UB926Q-Q1	0x2C

- Address 0x52 reserved for add-on/expansion board configuration EEPROM (WKUP\_I2C0).
- Address 0x10 & 0x11 are reserved for Apple Auth module (SoC\_I2C0).

## 4.4 GPIO Mapping

The general purpose IOs (GPIOs) of the SoC have two major groups as WKUP/MCU and MAIN. Table 4-3 describes the detailed GPIO mapping of SoC with EVM peripherals.

**Table 4-3. J7200 Soc - GPIO Mapping Table**

J7200 SoC - GPIO Mapping Table						
Package Signal Name	GPIO Number	Net name	Input/Output	Default	State	Remarks
<b>WKUP Domain</b>						
WKUP_GPIO0_0	WKUP_GPIO0_0	MCU_MCAN0_EN	Output	BOOTMODE	Active High	MCU CAN0 Enable
WKUP_GPIO0_1	WKUP_GPIO0_1	BOOT_EEPROM_WP	Output	BOOTMODE	Active High	Boot EEPROM Write protect
WKUP_GPIO0_2	WKUP_GPIO0_2	MCU_CAN1_STB	Output	BOOTMODE	Active High	MCU CAN1 Standby
WKUP_GPIO0_3	WKUP_GPIO0_3	GPIO MCU_RGMII1_RST#	Output	PU	Active low	MCU_RGMII1_Reset
WKUP_GPIO0_6	WKUP_GPIO0_6	OSPI/HYPER_MUX_SEL	Output	DIP_SEL	NA	Flash Memory Selection ('0' - OSPI0, '1' - Hyperflash + HyperRam)
WKUP_GPIO0_7	WKUP_GPIO0_7	SYS_IRQz	Input	PU	Active low	Push-button Interrupt, User Defined/Wake S2R ('0' - interrupt pending, '1' - normal operation)
MCU_OSPI0_LBCLK0	WKUP_GPIO0_17	MCU_OSPI0_ECC_FAIL	Output	NA	Active High	OSPI_ECC_FAIL (Mux option w/ MCU_HYPERBUS0_INT#),
MCU_SPI0_CLK	WKUP_GPIO0_56	PROFI_UART_SEL	Output	PD	Active High	Signal Mux Control ('0' - Profibus, '1' - BP/MC UART)
MCU_SPI0_D0	WKUP_GPIO0_57	SYS_MCU_PWRDN	Output	PD	Active low	System Power Down ('0' - normal operation, '1' - system power down)
MCU_SPI0_D1	WKUP_GPIO0_58	MCU_CAN0_STBz	Output	BOOTMODE	Active low	MCU CAN0 Standby
MCU_SPI0_CS0	WKUP_GPIO0_59	MCU_RGMII1_INT#	Input	PU	Active Low	MCU Ethernet Interrupt ('0' - interrupt pending, '1' - no interrupt)
WKUP_GPIO0_77	WKUP_GPIO0_77	WKUP_GPIO0_77	Output	BOOTMODE	NA	Open (GPIO not used)
WKUP_GPIO0_78	WKUP_GPIO0_78	H_MAIN_GPIO_A	Output	BOOTMODE	NA	Open (GPIO not used)
WKUP_GPIO0_80	WKUP_GPIO0_80	LSM6DSOX_INT	Output	BOOTMODE	NA	Open (GPIO not used)
WKUP_GPIO0_84	WKUP_GPIO0_84	H MCU_INT#	Input	PU	Active low	Interrupt from PMIC
<b>Main Domain</b>						
EXTINTn	GPIO0_0	SOC_EXTINTN	Input	PU	Active low	Push-button Interrupt, User Defined
MCAN1_RX	GPIO0_12	CANIO_RET_WAKE	Input	PU	NA	Push-button wake signal,
MCAN9_RX	GPIO0_28	GPIO_RGMII2_RST	I/O	NA	NA	Routed to INFO/GESI expansion connector. GESI - Used for GPIO_PRG0_RGMII_RST
MCAN7_RX	GPIO0_24	C_MCASP0_AFSR	NA	PU	Active low	I2C0 IO expander interrupt. ('0' - interrupt pending, '1' - no interrupt)(I2C0_IOEXP_INTERRUPT) Note: GPIO only available from Trace/GPMC Mux.
SPI0_D1	GPIO0_55	SEL_SDIO_3V3_1V8n	Output	PU	NA	SD Card IO Voltage Selection ('0' - 1.8 V, '1' - 3.3 V)
GPMC0_CLK	GPIO0_44	PM_I2C_SEL	Output	PD	NA	CP Board - PM I2C Mux selection. ('0' - SOC_I2C2_SCL/SDA -> PM1_SCL/SDA, '1' - SOC_I2C2_SCL/SDA -> PM2_SCL/SDA) GESI - Boosterpack_GPIO1
RMII1_CRS_DV	GPIO0_4	ENET_EXP_INTB	Input	PU	Active low	Ethernet Expansion Interrupt. ('0' - interrupt pending, '1' - no interrupt)

**Table 4-3. J7200 SoC - GPIO Mapping Table (continued)**

J7200 SoC - GPIO Mapping Table						
Package Signal Name	GPIO Number	Net name	Input/Output	Default	State	Remarks
MCAN9_TX	GPIO0_27	GPIO_RGMII2_INT#	Input	PU	Active low	Interrupt function. ('0' - interrupt pending, '1' - no interrupt) GESI - Used for PRG0_RGMII_INT#
GPIO Expander						
I2C0 ADDR: 0x21	P00	USB2.0_MUX_SEL	Output	PD	Active High	Signal Mux Control ('0' - USBC, '1' - USB Hub)
I2C0 ADDR: 0x21	P01	CANUART_MUX1_SEL0	Output	PD	Active High	Select line for CANUART MUX1
I2C0 ADDR: 0x21	P02	CANUART_MUX2_SEL0	Output	NA	Active High	Select line for CANUART MUX2
I2C0 ADDR: 0x21	P03	CANUART_MUX_SEL1	Output	PU	Active High	Select line shared for both through CANUART MUX
I2C0 ADDR: 0x21	P04	UART/LIN_MUX_SEL	Output	PD	Active High	Signal Mux Control ('0' - UART, '1' - LIN)
I2C0 ADDR: 0x21	P05	TRC_D17/AUDIO_REFCLK_SEL	Output	PU	Active High	Signal Mux Control ('0' - Audio_refclk, '1' - TRC_D17)
I2C0 ADDR: 0x21	P06	GPIO_LIN_EN	Output	PD	Active High	Enable signal for LIN Transceivers (GESI)
I2C0 ADDR: 0x21	P07	CAN_STB	Output	PD	Active High	Standby signals for CAN Transceivers (GESI)

## 4.5 Power Supply

Figure 4-3 shows the SoM's power distribution system. The Power to the SoM is derived from the Dual Buck converter 12 V to 5.0 V/3.3 V on the Common Processor Board. The J7200 processor is powered from a TPS6594x + LP8764x PMIC solution, which is optimized for the J7200 to support a wide variety of use cases.

Buck regulator TPS62811-Q1 used for the generation of LPDDR4 IO power supply and DIP SW4.1 used for selecting the IO supply to support LPDDR4/4x (1.1 V/0.6 V).

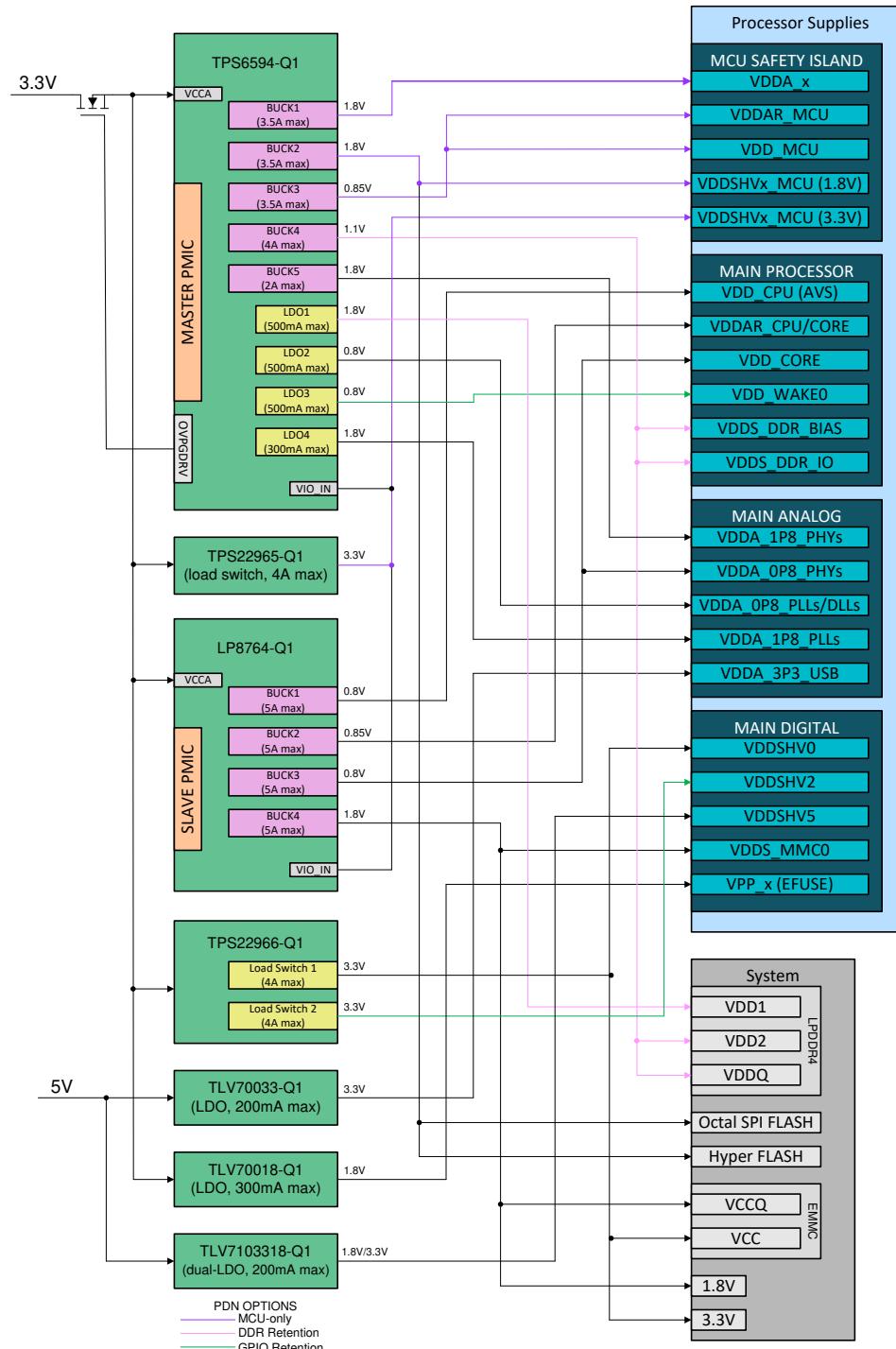


Figure 4-3. J7200 SOM Power Distribution Block Diagram

#### 4.5.1 Power Sequencing

Figure 4-4 shows the power flow and power up sequence for all the discrete supplies on the EVM. Note processor specific power supplies are provided from the Dual PMICs, and its specific power sequence is to support the processor sequence requirements. This sequence is documented in the device-specific processor's data manual. Figure 4-4 illustrates the support of all the other system supplies.

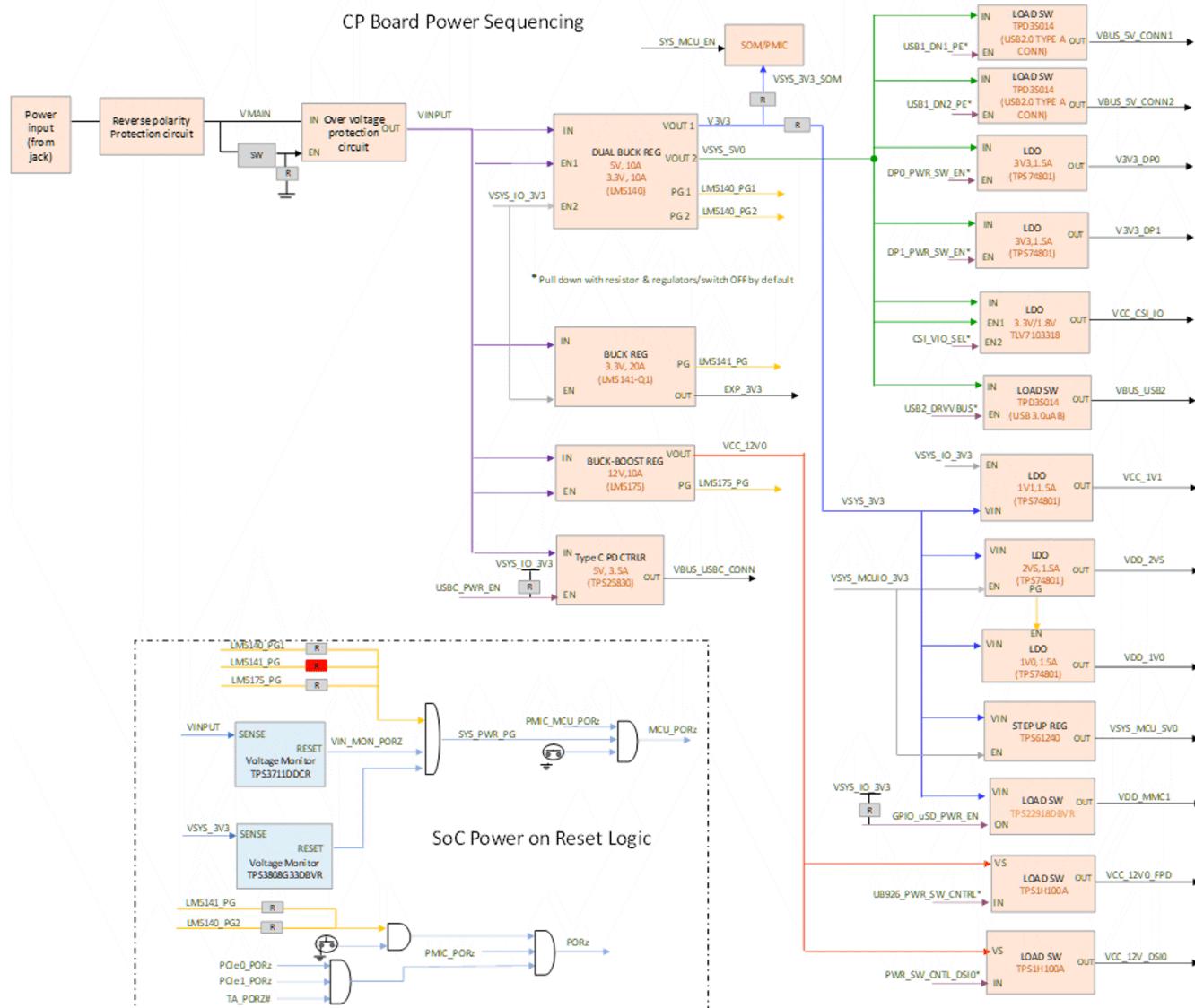


Figure 4-4. Power ON Sequencing

#### 4.5.2 Voltage Supervisor

The power rails are monitored to control the Power ON Reset (MCU\_PORz) for SOC. Two supervisor devices are provided to monitor Main power input and VSYS\_3V3.

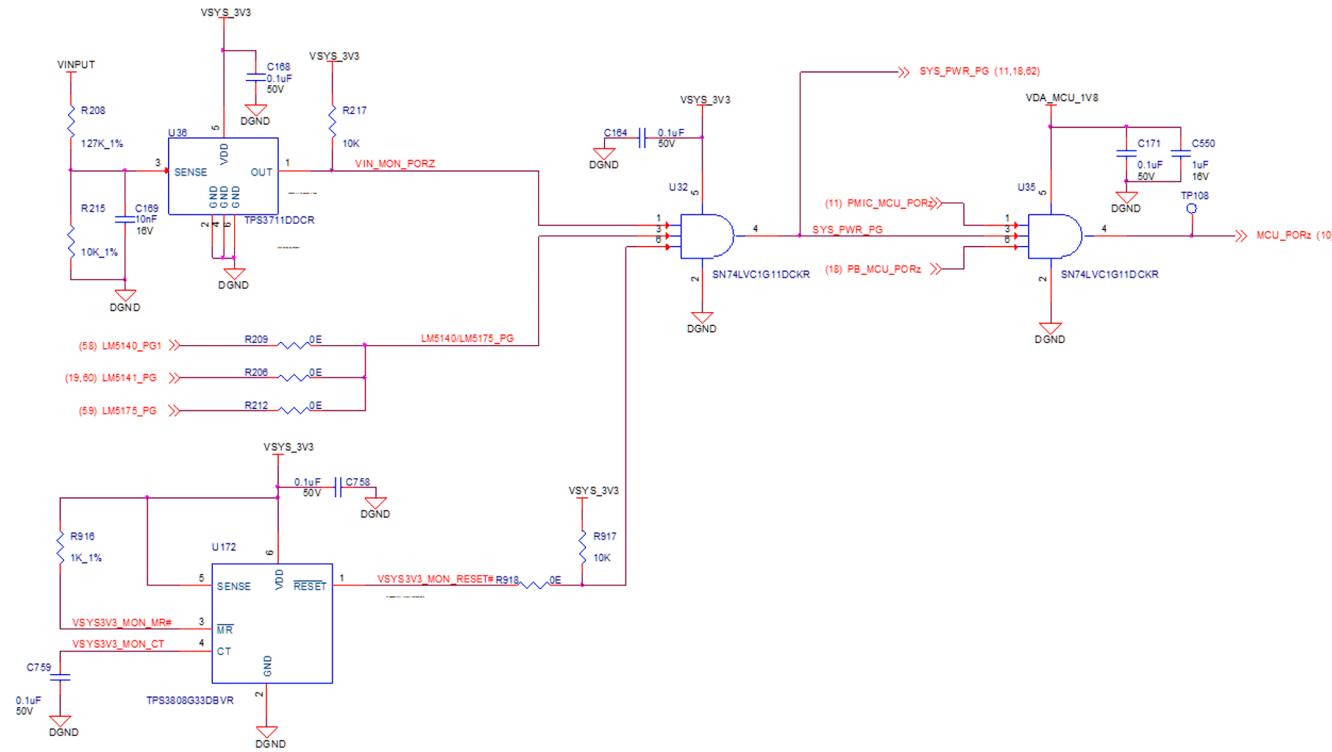


Figure 4-5. Voltage Supervisor Circuit

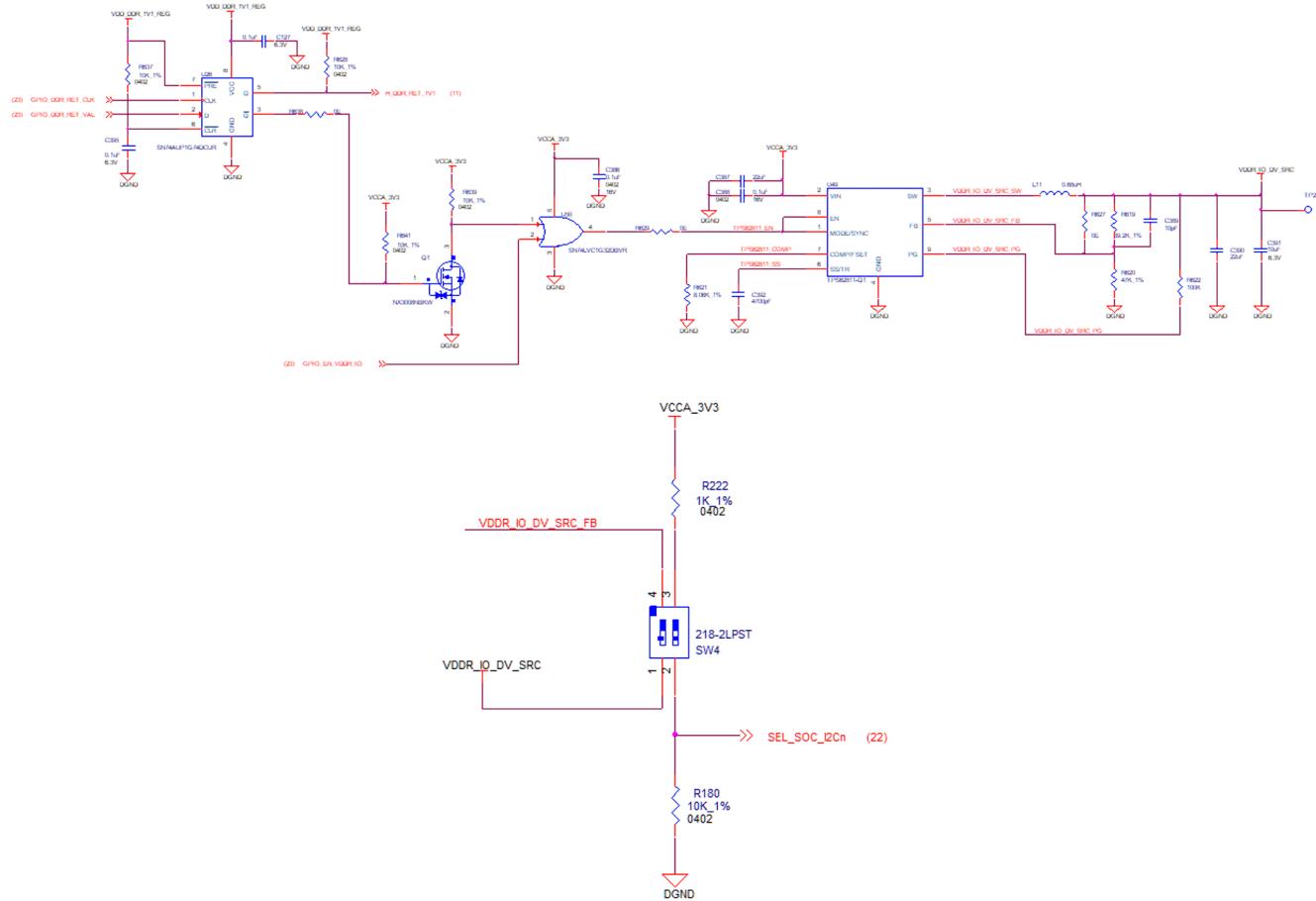
#### 4.5.3 DDR I/O Voltage Selection

There is a DIP switch provided on the J7200 SoM to select the SoC's DDR and LPDDR4 memory IO supply for the LPDDR4/ LPDDR4x.

The DIP switch SW4 Bit 1 provides an option to change the feedback path of regulator (U49) that decides the output supply voltages.

**Table 4-4. J7200 DDR IO Voltage Selection**

SW4 Bit 1	SDRAM_TYPE	Selected DDR IO Voltage
OPEN/LOW	LPDDR4	1.1 V
CLOSE/HIGH	LPDDR4x	0.6 V



**Figure 4-6. DDR I/O Voltage Selection**

Currently, the J7200 device does not support LPDDR4x. This support may be added at a later date. The EVM does support this feature if/when support is added to the silicon.

#### 4.5.4 J7200 SoC SLEEP Logic Operation

The EVM supports a low power state referred to as SLEEP. This state allows the processor (or optionally the entire system) to be powered off. The power state is managed through the PMIC(s). [Table 4-5](#) shows the steps required to enter the SLEEP state.

**Table 4-5. J7200 SoC SLEEP Logic Flow**

PMIC Transition From Active Mode to SLEEP Mode				
Action	Address	Bits	Data	Register/Bit Names
Unmask MASK_GPIO9_11 on PMIC (I2CID: 0x48)	0x51	[5:0]	0x2F	MASK_GPIO9_11
Read and write default values of INT_GPIO to clear the WKUP1 interrupt	0x63	[7:0]	Read value	INT_GPIO
Reconfigure GPIO4 of Leo to LP_WKUP1	0x34	[7:0]	0xC8	GPIO4_CONFIG
Set GPIO4_RISE_MASK to '0' to enable CAN_WKUP	0x50	[3]	0x0	GPIO4_RISE_MASK
Read and write default values of GPIO_INT to clear the LP_WKUP1 interrupt	0x64	[7:0]	Read value	GPIO_INT
Set nSLEEP2b and nSLEEP1b to '00' to go to S2R state	0x86	[1:0]	0x0	NSLEEP2b, NSLEEP1b
Read and write to clear the ENABLE_INT interrupt	0x65	[1]	0x1	ENABLE_INT

The EVM can be woke from the low power state either by pressing the CAN\_WAKEn button (SW12).

#### 4.5.5 J7200 SoC MCU Only Operation

The EVM supports low power state referred to as MCU only. This state allows the MCU domain of the processor to remain on/active while the rest of the system is powered off. The power state is managed through the PMIC(s). [Table 4-6](#) shows the steps required to enter the MCU only state.

**Table 4-6. J7200 SoC MCU only Logic Flow**

PMIC Transition From Active Mode to MCU Only Mode				
Action	Address	Bits	Data	Register/Bit Names
Unmask MASK_GPIO9_11 on PMIC (I2CID: 0x48)	0x51	[5:0]	0x2F	MASK_GPIO9_11
Read and write default values of INT_GPIO to clear the WKUP1 interrupt	0x63	[7:0]	Read value	INT_GPIO
Reconfigure GPIO4 of Leo to LP_WKUP1	0x34	[7:0]	0xC8	GPIO4_CONFIG
Set GPIO4_RISE_MASK to '0' to enable CAN_WKUP	0x50	[3]	0x0	GPIO4_RISE_MASK
Read and write to clear the LP_WKUP1 interrupt	0x64	[7:0]	0x08	GPIO_INT
Set nSLEEP2b and nSLEEP1b to '00' to go to S2R state	0x86	[1:0]	0x02	NSLEEP2b, NSLEEP1b
Read and write to clear the ENABLE_INT interrupt from Leo (I2CID: 0x48)	0x65	[1]	0x1	ENABLE_INT
Read and write to clear the ENABLE_INT interrupt from Hera (I2CID: 0x4C)	0x65	[1]	0x1	ENABLE_INT

The EVM can be woke from the low power state either by pressing the CAN\_WAKEn button (SW12) or by issuing commands to the PMIC through I2C.

#### 4.5.6 J7200 SoC GPIO Retention Operation

The EVM supports low power state referred to as GPIO Retention mode. This state allows the CANIO domain of the processor to remain on/active while the rest of the system is powered off. The power state is managed through the PMIC(s). [Table 4-7](#) shows the steps required to enter the GPIO Retention state.

**Table 4-7. J7200 SoC GPIO Retentions Logic Flow**

PMIC Transition From Active Mode to GPIO Retention Mode				
Action	Address	Bits	Data	Register/Bit Names
Unmask MASK_GPIO9_11 on PMIC (I2CID: 0x48)	0x51	[5:0]	0x2F	MASK_GPIO9_11
Read and write default values of INT_GPIO to clear the WKUP1 interrupt	0x63	[7:0]	Read value	INT_GPIO
Reconfigure GPIO4 of Leo to LP_WKUP1	0x34	[7:0]	0xC8	GPIO4_CONFIG
Set GPIO4_RISE_MASK to '0' to enable CAN_WKUP	0x50	[3]	0x0	GPIO4_RISE_MASK
Read and write default values of GPIO_INT to clear the LP_WKUP1 interrupt	0x64	[7:0]	Read value	GPIO_INT
Set TRIGGER_I2C_6 on Leo to '1' to enable (I2CID: 0x48)	0x85	[6]	0x40	FSM_I2C_TRIGGER
Set TRIGGER_I2C_6 on Hera to '1' to enable (I2CID: 0x4C)	0x85	[6]	0x40	FSM_I2C_TRIGGER
Read and write to clear the ENABLE_INT interrupt	0x65	[1]	0x1	ENABLE_INT

The EVM can be woken from the low power state either by configuring the SoC's IO chain to wake from either CAN message (MCAN0 on connector J1) or GPIO (GPIO0\_12 on button SW1).

#### 4.5.7 J7200 SoC DDR Retention Operation

The EVM supports a low power state referred to as DDR retention. This state allows the processor (or optionally the entire system) to be powered off while the LPDDR4 memory is maintained in self refresh mode. The power state is managed through the PMIC(s). [Table 23](#) shows the steps required to enter the DDR retention state.

**Table 4-8. J7200 DDR Retention Logic Flow**

PMIC Transition From Active Mode to DDR Retention Mode				
Action	Address	Bits	Data	Register/Bit Names
Unmask MASK_GPIO9_11 on PMIC (I2CID: 0x48)	0x51	[5:0]	0x2F	MASK_GPIO9_11
Read and write default values of INT_GPIO to clear the WKUP1 interrupt	0x63	[7:0]	Read value	INT_GPIO
Set GPIO2 & GPIO3 to GPIO mode	0x32, 0x33	[7:0]	0xD	GPIO2_CONF GPIO3_CONF
Write '1' to GPIO2_OUT	0x3D	[7:0]	0x2	GPIO_OUT_1
Write '1' to GPIO2_OUT and GPIO3_OUT	0x3D	[7:0]	0x06	GPIO_OUT_1
Reconfigure GPIO4 of Leo to LP_WKUP1	0x34	[7:0]	0xC8	GPIO4_CONFIG
Set GPIO4_RISE_MASK to '0' to enable CAN_WKUP	0x50	[3]	0x0	GPIO4_RISE_MASK
Read and write default values of GPIO_INT to clear the LP_WKUP1 interrupt	0x64	[7:0]	Read value	GPIO_INT
Set TRIGGER_I2C_7 on Leo to '1' to enable (I2CID: 0x48)	0x85	[7]	0x80	FSM_I2C_TRIGGER
Set TRIGGER_I2C_7 on Hera to '1' to enable (I2CID: 0x4C)	0x85	[7]	0x80	FSM_I2C_TRIGGER
Set nSLEEP2b and nSLEEP1b to '00' to go to S2R state	0x86	[1:0]	0x0	NSLEEP2b, NSLEEP1b
Read and write to clear the ENABLE_INT interrupt	0x65	[1]	0x1	ENABLE_INT

The EVM can be woke from the low power state either by pressing the CAN\_WAKEn button (SW12) or by issuing commands to the PMIC through I2C.

#### 4.5.8 Power Monitoring

INA226 power monitor devices are used to monitor current and voltage of various power rails of J7200 processor. The device reports current, voltage and power to J7200 processor through I2C interface. Four Terminal High Precision shunt resistors are provided, and the values are calculated based on load current.

**Table 4-9. INA Devices I2C Slave Address**

POWER SOURCE	SUPPLY NET	I2C Bus	SLAVE ADDRESS (IN HEX)	Value of the Shunt Connected to the Supply Rail
VDD_MCU_0V85_REG	VDD_MCU_0V85	SOC_I2C2/PM1	0x40	0.01E
VDD_MCU_0V85_REG	VDD_MCU_RAM_0V85	SOC_I2C2/PM1	0x41	0.01E
VDA_MCU_1V8_REG	VDA_MCU_1V8	SOC_I2C2/PM1	0x42	0.01E
VDD MCUIO_3V3_LS	VDD MCUIO_3V3	SOC_I2C2/PM1	0x43	0.01E
VDD MCUIO_1V8_REG	VDD MCUIO_1V8	SOC_I2C2/PM1	0x44	0.01E
VDD_CORE_0V8_REG	VDD_CORE_0V8	SOC_I2C2/PM1	0x45	0.005E
VDD_RAM_0V85_REG	VDD_RAM_0V85	SOC_I2C2/PM1	0x46	0.01E
VDD_WK_0V8_REG	VDD_WK_0V8	SOC_I2C2/PM1	0x47	0.01E
VDD_CPU_AVG_REG	VDD_CPU_AVG	SOC_I2C2/PM1	0x48	0.01E
VDD_DDR_1V1_REG	VDDR_BIAS_1V1	SOC_I2C2/PM1	0x49	0.01E
VDDR_IO_DV_SRC	VDDR_IO_DV	SOC_I2C2/PM1	0x4A	0.01E
VDD_CORE_0V8	VDD_PHYCORE_0V8	SOC_I2C2/PM1	0x4B	0.01E
VDA_PLL_1V8_REG	VDA_PLL_1V8	SOC_I2C2/PM1	0x4C	0.01E
VDD_PHY_1V8_REG	VDD_PHY_1V8	SOC_I2C2/PM1	0x4D	0.01E
VDD_USB_3V3_REG	VDA_USB_3V3	SOC_I2C2/PM1	0x4E	0.01E
VDD_GPIORET_3V3	VDD_GPIORET_3V3	SOC_I2C2/PM1	0x4F	0.01E
VDD_IO_1V8_REG	VDD_IO_1V8	SOC_I2C2/PM2	0x40	0.01E
VDD_IO_3V3_LS	VDD_IO_3V3	SOC_I2C2/PM2	0x41	0.01E
VDD_SD_DV_REG	VDD_SD_DV	SOC_I2C2/PM2	0x42	0.01E
VDD1_LPDDR4_1V8_REG	VDD1_LPDDR4_1V8	SOC_I2C2/PM2	0x43	0.01E
VDD_DDR_1V1_REG	VDD2_LPDDR4_1V1	SOC_I2C2/PM2	0x44	0.01E
VDDR_IO_DV_SRC	VDDQ_LPDDR4_DV	SOC_I2C2/PM2	0x45	0.01E
VDD_MCUIO_1V8_REG	VSYS_MCUIO_1V8	SOC_I2C2/PM2	0x46	0.01E
VDD_MCUIO_3V3_LS	VSYS_MCUIO_3V3	SOC_I2C2/PM2	0x47	0.01E
VDD_IO_1V8_REG	VSYS_IO_1V8	SOC_I2C2/PM2	0x48	0.01E
VDD_IO_3V3_LS	VSYS_IO_3V3	SOC_I2C2/PM2	0x49	0.01E
VCC_12V0	VCC_12V0	SOC_I2C2/PM2	0x4A	0.01E
VSYS_5V0	VSYS_5V0	SOC_I2C2/PM2	0x4B	0.01E
VSYS_3V3	VSYS_3V3	SOC_I2C2/PM2	0x4C	0.005E
VSYS_3V3	VSYS_3V3_SOM	SOC_I2C2/PM2	0x4D	0.01E
VDA_DLL_0V8_REG	VDA_DLL_0V8	SOC_I2C2/PM2	0x4E	0.01E
EXP_3V3	EXP_3V3	SOC_I2C2/PM2	0x4F	0.01E

INA devices can be accessed from the processor through Main I2C2 instance. Also, there is an option to Monitor the SoC and peripheral powers using external I2C Master.

Common processor has five-pin header (J12) with isolation circuit to interface the INA devices with external I2C Master. Buffer IC SN74CB3Q3125PWR (U69) is used to isolate the External I2C connections from the INA devices. The control of this buffer is provided from SYS\_PWR\_PG, which is enabled by default on power up.

External Power Monitor header details:

Mfr. Part# 68002-205HL (CON HDR 1X5 2.54MM PITCH ST TH)

**Table 4-10. External Power Monitor Header Pinouts**

Header (J12) Pin Number	Signal Name
1	CON_PM1_SCL
2	CON_PM1_SDA
3	DGND
4	CON_PM2_SDA
5	CON_PM2_SCL

Test automation header on the Common processor board also can access these INA devices externally.

#### 4.5.9 Power Test Points

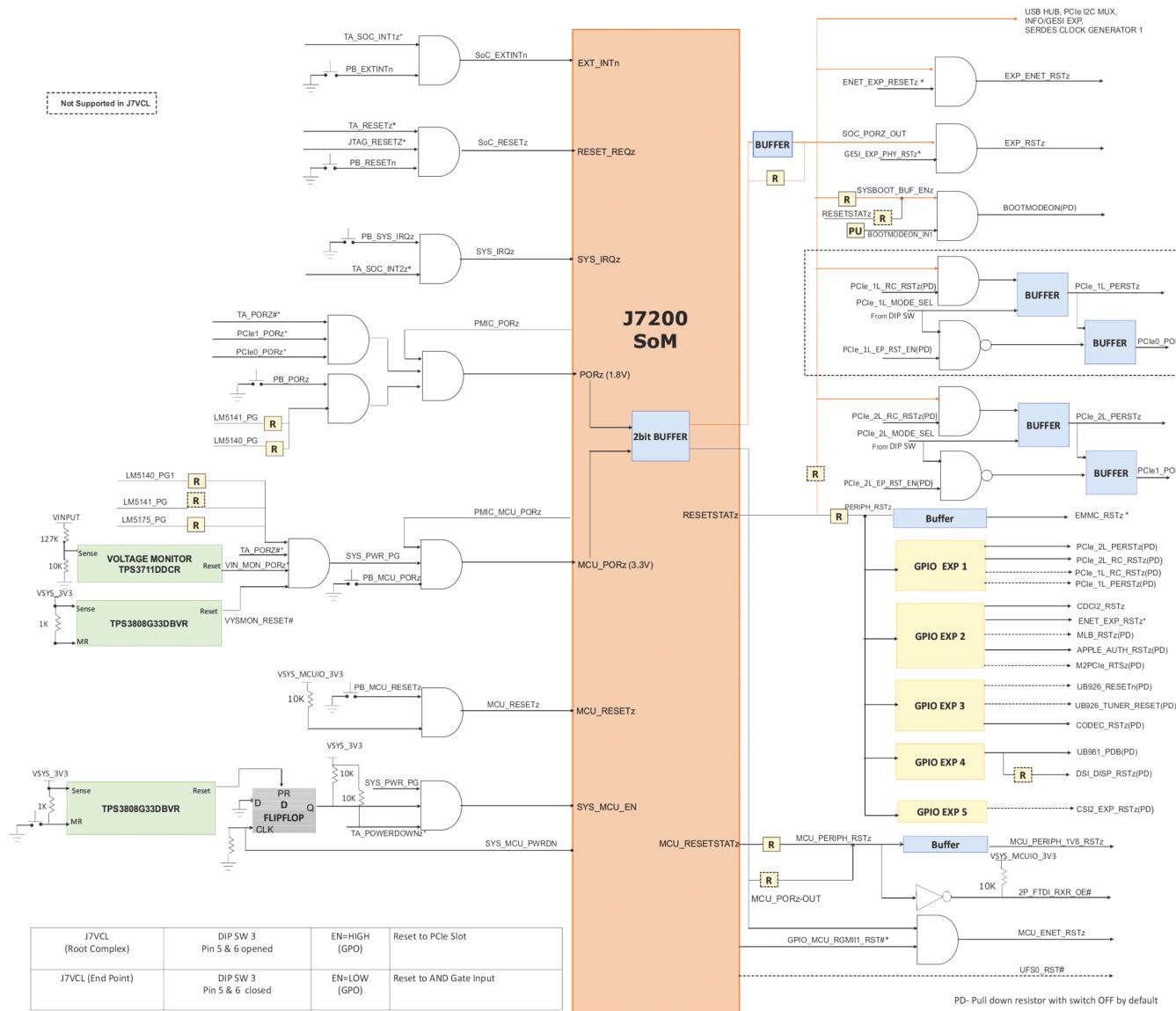
Test points for each system power rails are provided on the Common Processor Board (CPB) and are mentioned in [Table 4-11](#). Location for each can be identified by searching the assembly drawing for the test point reference number.

**Table 4-11. Power Test Points**

Power Supply	Test Point	Nominal Voltage
VINPUT	TP20	12.0 V
VSYS_3V3	TP130	3.3 V
VCC_12V0	TP39	12.0 V
VSYS_5V0	TP26	5.0 V
EXP_3V3	TP43	3.3 V
VDD_2V5	TP63	2.5 V
VDD_1V0	TP59	1.0 V
VCC_1V1	TP60	1.1 V
VSYS MCU 5V0	TP117	5.0 V
VDD_SD_DV	TP44	3.3 V
VSYS_MCUIO_3V3	TP113	3.3 V
VSYS_IO_3V3	TP131	3.3 V
VSYS_MCUIO_1V8	TP134	1.8V
VSYS_IO_1V8	TP132	1.8V
VDA MCU 1V8	TP105	1.8V

## 4.6 Reset

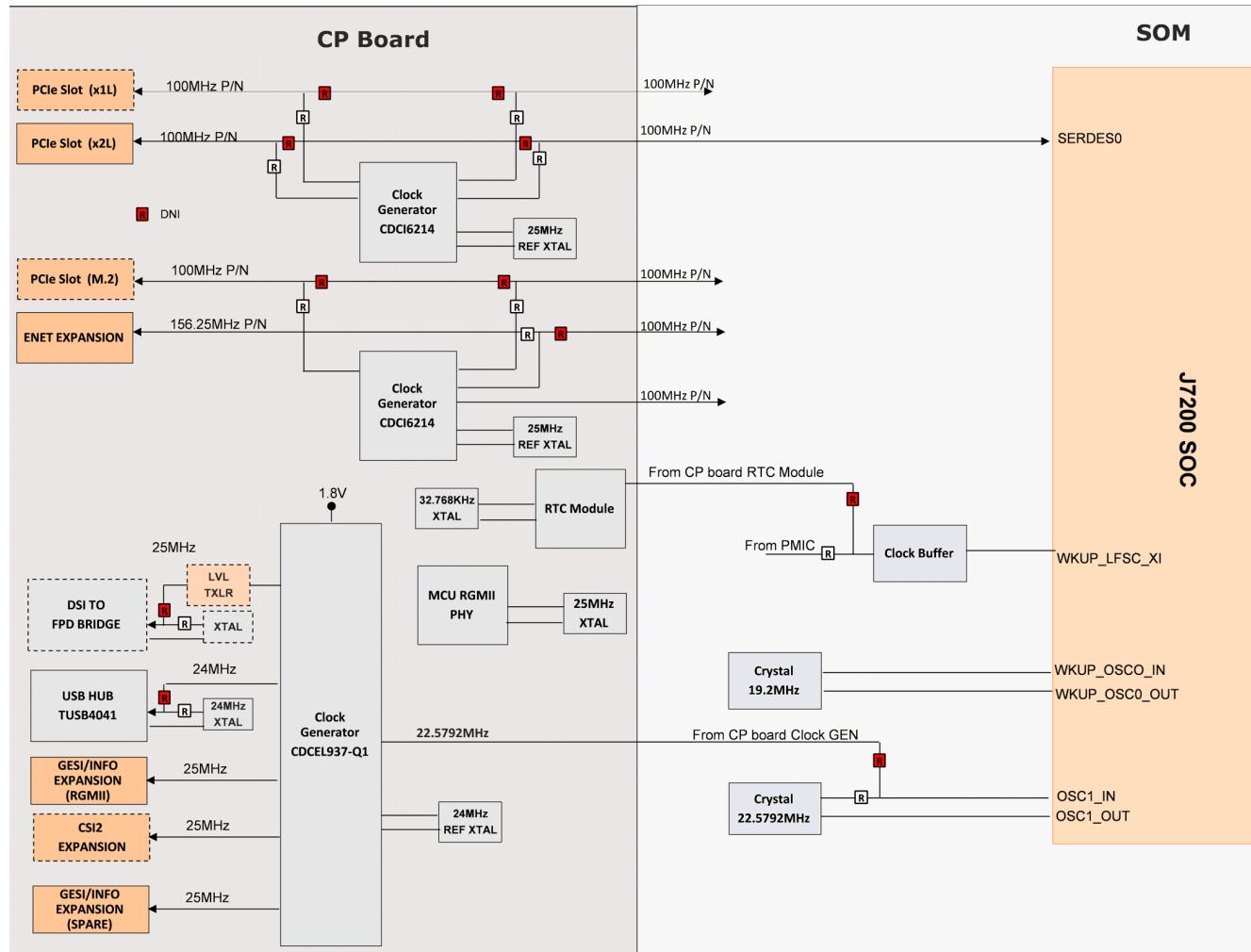
Figure 4-7 shows the J7200 EVM reset architecture.



**Figure 4-7. EVM Reset Architecture**

## 4.7 Clock

Figure 4-8 shows the J7200 EVM clock architecture.

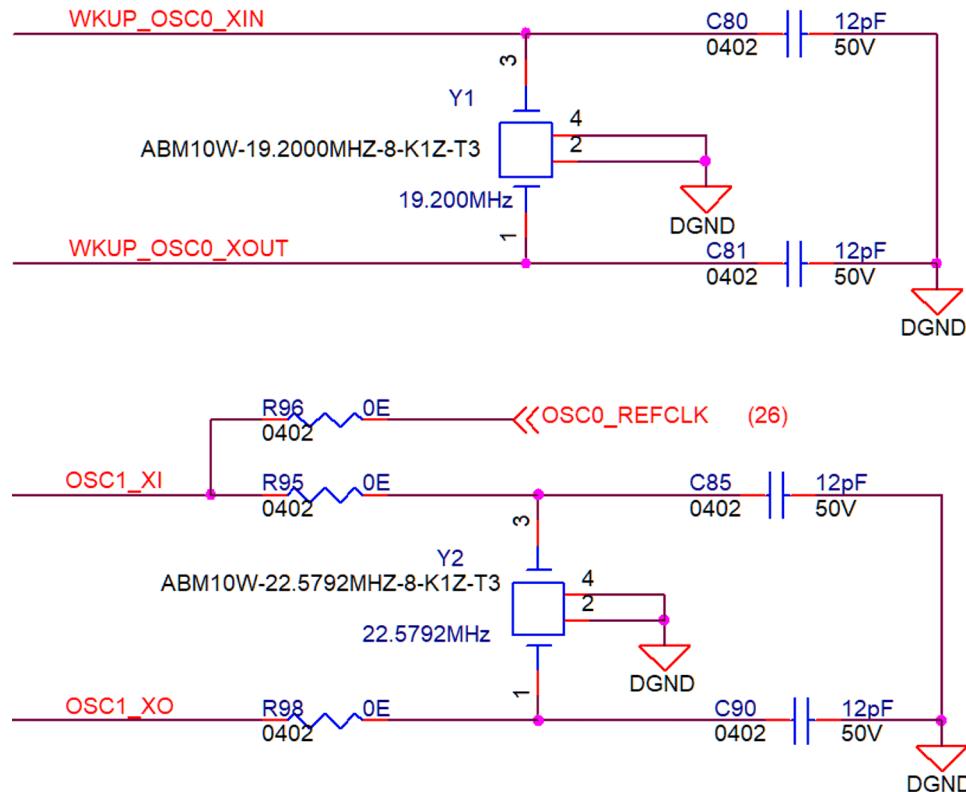


**Figure 4-8. EVM Clock Architecture**

EVM supports multiple Crystals and Clock generator to provide the reference clock input to the SoC and EVM peripherals. Non-supported peripherals are highlighted in dashed lines.

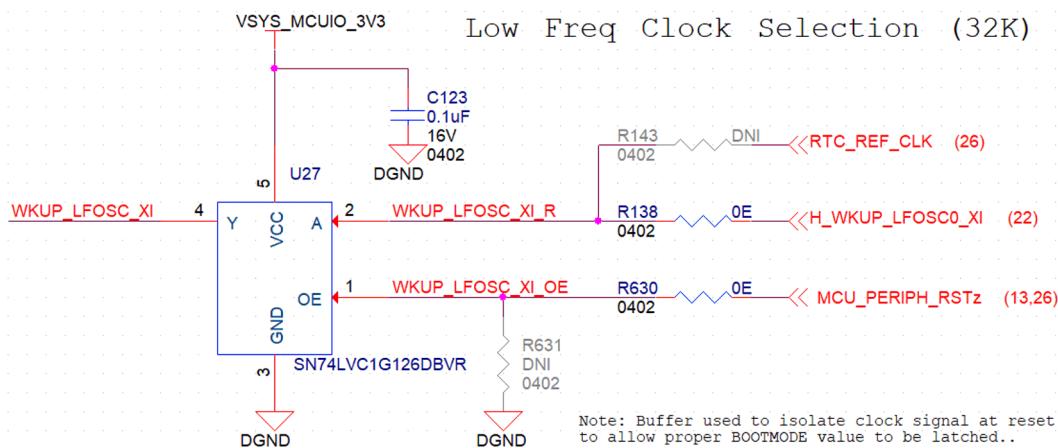
#### 4.7.1 Processor's Primary Clock

There are two external crystals attached to the J7200 processor to provide the SoC's Primary clocks WKUP\_OSC0 (19.2 MHz) and OSC1 (22.5792 MHz) as shown in [Figure 4-9](#).



**Figure 4-9. J7200 SoC Primary Clock**

The WKUP\_OSC0 is required by the processor. OSC1 is an optional clock (not required for J7200 processing). A third low frequency clock (32 KHz) can be used for various sleep timers. It is optional (not required for J7200 processing) and can be optionally sourced from PMIC or RTC module as shown in [Figure 4-10](#).



**Figure 4-10. WKUP\_OSC0 Enable Circuit**

#### 4.7.2 Processor's Secondary/SERDES Ref Clock

In addition to the Primary clock, the SERDES reference clocks to the SoC is sourced from the Clock Generator (CDCI6214) on the Common processor board. All these clocks are 100MHz with HCSL level for the SoC's SERDES reference clock input. The programming of CDCI6214 chip is done through J7200 SoC's I2C0 port.

There are two CDCI6214 clock generators available to source the SERDES reference clocks to SoC. The CDCI1 (U22) is not connected to I2C0 port by default. The clocks from CDCI1 (U22) is derived using factory programmed configuration.

Only the CDCI2 (U17) is required I2C programming for the desired clock outs from each channel. A 25 MHz crystal is attached the each CDCI chip for its reference clock inputs.

**Table 4-12. Processor's Secondary/SERDES Ref Clock**

Signal/Net Name	Probe Point	Clock Gen/CH	Description	Frequency
CLKGEN_SERDES1_REFCLK_P/N	R176/R167	CDCI1/Y1	100 MHz HCSL Clock to SoC SERDES1	100 MHz
CLKGEN_PCIE0_1L_REFCLK_P/N <sup>(1)</sup>	R143/ R142	CDCI1/Y2	100 MHz HCSL Clock to PCIe0 x1 L Socket	100 MHz
CLKGEN_SERDES0_REFCLK_P/N <sup>(1)</sup>	R145/ R153	CDCI1/Y3	100 MHz HCSL Clock to SoC SERDES0	100 MHz
CLKGEN_PCIE0_2L_REFCLK_P/N	R168/R177	CDCI1/Y4	100 MHz HCSL Clock to PCIe0 x2 L Socket	100 MHz
CLKGEN_SERDES2_REFCLK_P/N	R158/R157	CDCI2/Y1	100 MHz HCSL Clock to SoC SERDES2	100 MHz
CLKGEN_USB_REFCLK_P/N <sup>(1)</sup>	R160/ R159	CDCI2/Y2	100 MHz HCSL Clock to SoC USB	100 MHz
QSGMII_PHY_REFCLK_P/N	C108/C109	CDCI2/Y3	156.25 MHz LVDS Clock to Ethernet Expansion board	156.25 MHz
CLKGEN_PCIE2_2L_REFCLK_P/N <sup>(1)</sup>	R123/ R124	CDCI2/Y4	100 MHz HCSL Clock to PCIe M.2 Socket	100 MHz

- These clocks are currently unused in J7200 EVM system.

The probe points mentioned above are with reference to Common processor board.

#### 4.7.3 EVM Peripheral Ref Clock

The reference clocks to the EVM peripherals are sourced by the Clock generator (CDCEL937PWR) on the Common processor board. Which is programmed through I2C0 port of processor. A 24MHz crystal is attached to this clock generator to derive the desired clock outputs.

**Table 4-13. EVM Peripheral Ref Clock**

Signal/Net Name	Probe Point	Clock Gen/Ch	Description	Frequency
USB1_HUB_REFCLK	R80	CDCEL/Y1	24 MHz clock for USB Hub (not used by default)	24 MHz
DSI_REFCLK_1V8 <sup>(1)</sup>	R92	CDCEL/Y2	25 MHz clock for DSI transmitter ('941A)	25 MHz
QSGMII_REFCLK	R81	CDCEL/Y3	25 MHz clock for Ethernet Expansion Board	25 MHz
RGMII_REFCLK	R100	CDCEL/Y4	25 MHz clock for Expansion Board	25 MHz
CSI2_REFCLK <sup>(1)</sup>	R101	CDCEL/Y5	25 MHz clock for CSI2 Expansion Board	25 MHz
OSC0_REFCLK	R82	CDCEL/Y6	22.5782 MHz clock for SoC (not used by default)	22.5782 MHz
EXP_REFCLK	R83	CDCEL/Y7	<not currently used>	24 MHz

- These clocks are currently unused in J7200 EVM system.

The probe points mentioned above are with reference to Common processor board.

## 4.8 Memory Interfaces

### 4.8.1 LPDDR4 Interface

The J7200 SOM has 4GB of LPDDR4 using single 32Gb x8bit wide memory devices arranged in an 32bit wide bus. The LPDDR4 interface can operate up to 3200 Mb/s speed. The LPDDR4 devices are connected using T routing for the clock lines and point-to-point connection for the data bus, address/command lines.

The Micron's LPDDR4 memory chip MT53D1024M32D4DT is used on the SoM, it requires 1.8 V for Core (VDD1), 1.1 V for Core2 (VDD2) and 1.1 V for I/O buffer power (VDDQ).

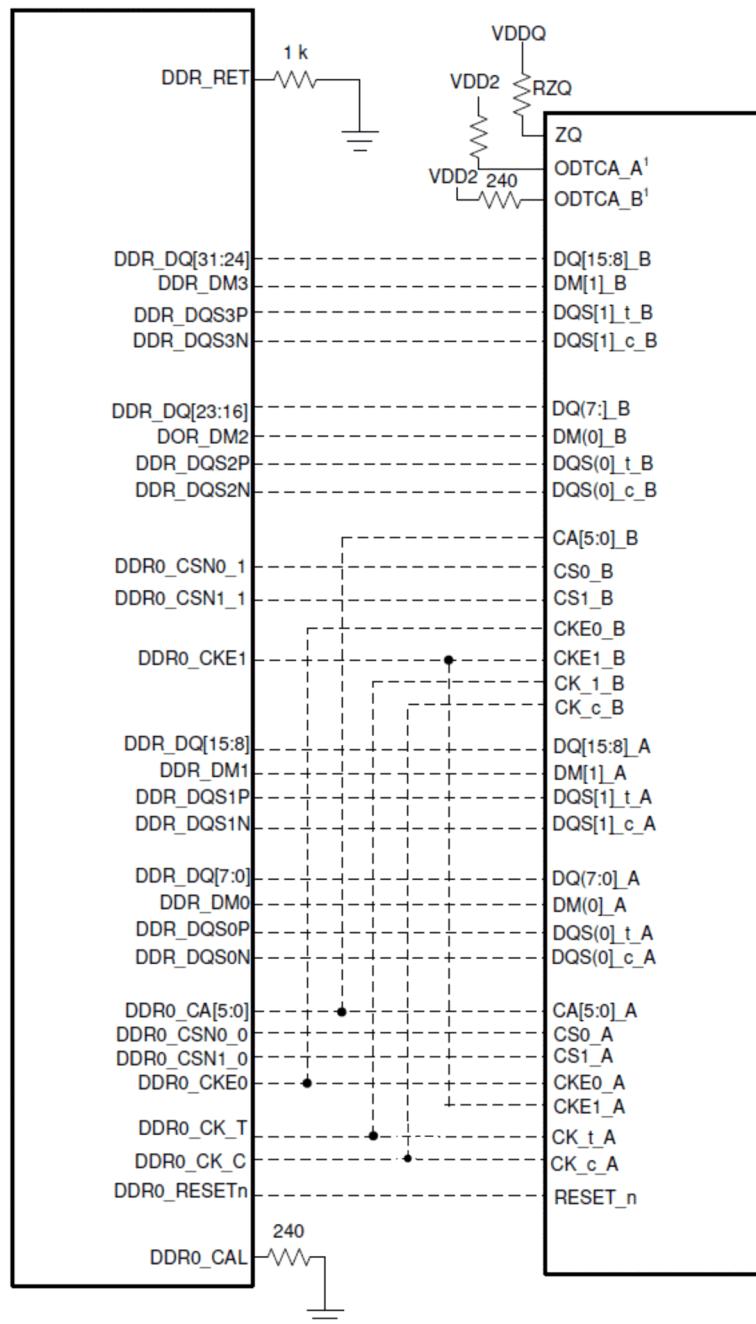


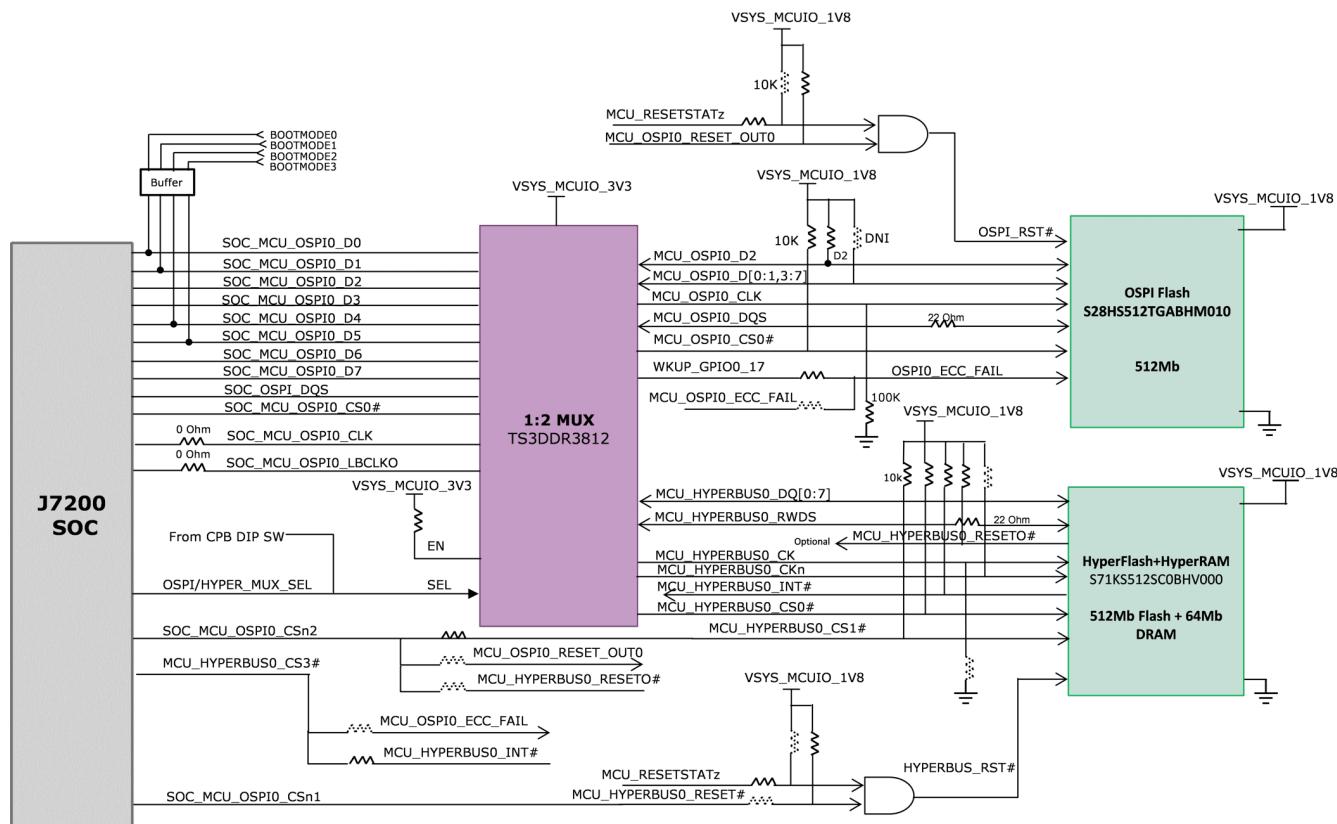
Figure 4-11. J7200 SoM LPDDR4

#### 4.8.2 OSPI Interface

The J7200 SOM has 512-Mbit OSPI memory device of part number S28HS512TGABHM010 connected to OSPI0 interface of J7200 processor. The OSPI interface supports single and double data rates with memory speed up to 166 MHz SDR and 200 MHz DDR.

J7200 SOM is xSPI compliant, specifically JEDEC eXpanded SPI (JESD251) compliant.

The SOM board also supports an option to include Hyper Flash + Hyper RAM Mfr. Part# S71KS512SC0, which is a 512Mb flash + 64Mb DRAM. 12-bit Active mux TS3DDR3812RUAR is provided to select either OSPI or HBMC interface. The selection of OSPI and hyper flash will be done by using a DIP (SW3) switch which is populated on the CP board. For more details, see [Section 3.4.1](#).



**Figure 4-12. J7200 SoM OSPI and Hyper Flash**

#### 4.8.3 MMC Interface

The processor supports two MMC (MMC0 and 1) ports. MMC0 is connected to eMMC flash and MMC1 is interfaced with Micro SD Socket on the Common processor board.

##### 4.8.3.1 MMC0 - eMMC Interface

A 16GB, V5.1 compliant eMMC Flash memory Mfr. Part# MTFC16GAPALBH-AAT ES is interfaced to MMC0 port of the J7200 SoC. The flash is connected to 8 bits of the MMC0 interface supporting HS400 double data rates up to 200 MHz. External pull up resistors 49.9K are provided on DATA [7:0], CMD and Reset signals. The pull-down resistor is provided on the data strobe signal to prevent bus floating.

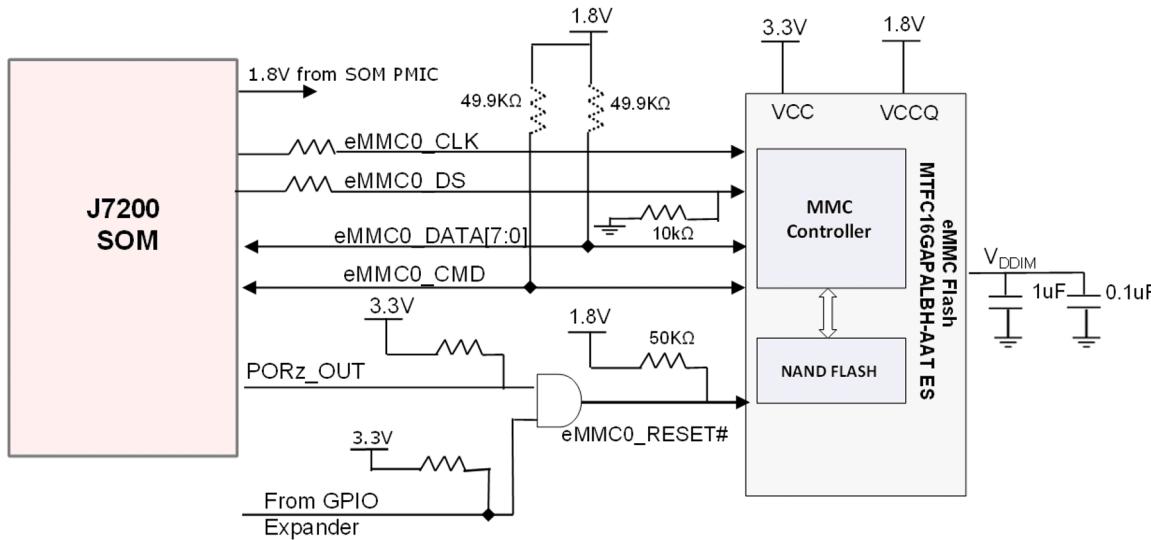
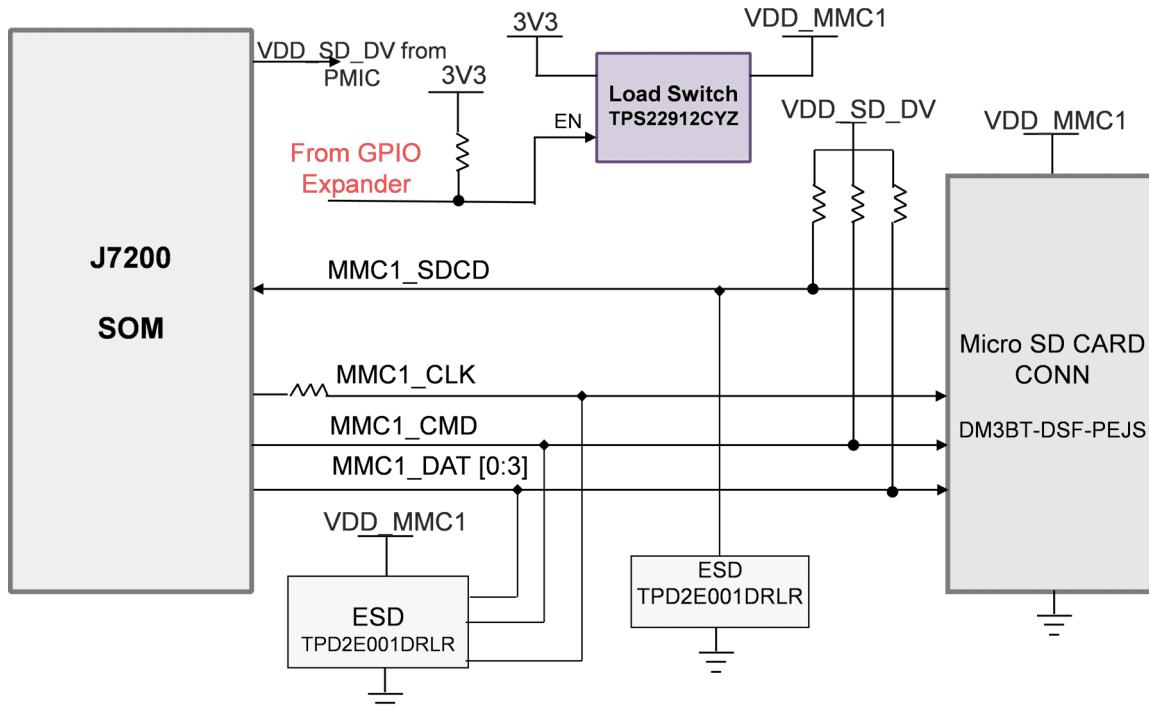


Figure 4-13. eMMC Memory Block Diagram

#### 4.8.3.2 MMC1 – Micro SD Interface

The EVM supports a Micro SD card interface connected to MMC1 port of SoC. The Micro SD card socket Mfr. Part# DM3BT-DSF-PEJS is interfaced with MMC1 port of SoC. This supports UHS1 operation including IO operations at both 1.8 V and 3.3 V. The Micro SD card interface is set to operate in SD mode by default.

The IO voltage for the MMC1 port is derived from the discrete LDO (TLV7103318), which is controlled by SEL\_SDIO\_3V3\_1V8n (GPIO0\_55). The SD Card power is provided using a load switch, which is controlled by a GPIO from IO expander. Control signal “GPIO\_uSD\_PWR\_EN” is driven by the I2C IO expander U31 Port02 on the CP board. This IO expander is controlled by the processor’s I2C0 port. I2C address of the IO expander is 0x22.



**Figure 4-14. Micro-SD Card Block Diagram**

An ESD protection device Mfr. Part# TPD2E001DRLR is provided for data, clock, command and card detect signals. The CD (card detect) pin of Micro SD card socket is pulled high and connected to CD pin of SoC. An external pull up resistor (47K) is provided on data [3:0] and CMD signals to avoid floating.

#### 4.8.4 Board ID EEPROM Interface

The J7200 EVM boards are identified by its version and serial number, which are stored in the onboard EEPROM. The EEPROM is accessible from WKUP I2C0 port of J7200 processor.

The board ID EEPROM I2C slave address of various boards are listed in the I2C mapping table.

The J7200 SoM board includes a CAV24C256WEI2C EEPROM ID memory. The first 259 bytes of addressable EEPROM memory are pre-programmed with identification information for each board. The remaining 32509 bytes are available to the user for data or code storage.

Header	Field Name	Size (bytes)	Value for J7200 SOM	Comments
EE3355AA	MAGIC	4	0xEE3355AA	Magic Number
	TYPE	1	0x10	Fixed length and variable position board ID header
		2	37	Size of payload
BRD_INFO	TYPE	1	0x10	payload type
	Length	2	0x2E	Offset to next header
	Board_Name	16	J7200X-PM2-SOM	Name of the board
	Design_Rev	2	E6	Revision number of the design
	PROC_Nbr	4	105	PROC number
	Variant	2	0x3	Design variant number
	PCB_Rev	2	E6	Revision number of the PCB
	SCHBOM_Rev	2	0x0	Revision number of the schematic
	SWR_Rev	2	0x1	first software release number
	VendorID	2	0x1	
	Build_Week	2		Week of the year of production
	Build_Year	2		Year of production
	BoardID	6		
	Serial_Nbr	4		Incrementing board number
DDR_INFO	TYPE	1	0x11	
	Length	2	0x2	Offset to next header
	DDR control	2	0x7D60	DDR Control Word
MAC_ADDR	TYPE	1		payload type
	Length	2		Size of payload
	MAC control	2		MAC header control word
	MAC_adrs	192		
END_LIST	TYPE	1	0xFE	End Marker

#### 4.8.5 Boot EEPROM Interface

A 1-Mbit EEPROM is interfaced to MCU\_I2C0 for booting, I2C address set to 0x50, 0x51.

#### 4.9 MCU Ethernet Interface

The EVM includes RGMII connection between DP83867ERGZT Gigabit Ethernet PHY and the MCU domain network subsystem (NSS) of the Processor. RJ45 connector (J35) with Integrated magnetics LPJG163144NL is used.

A reference clock of 25 Mhz will be generated onboard using a crystal to DP83867ERGZT.

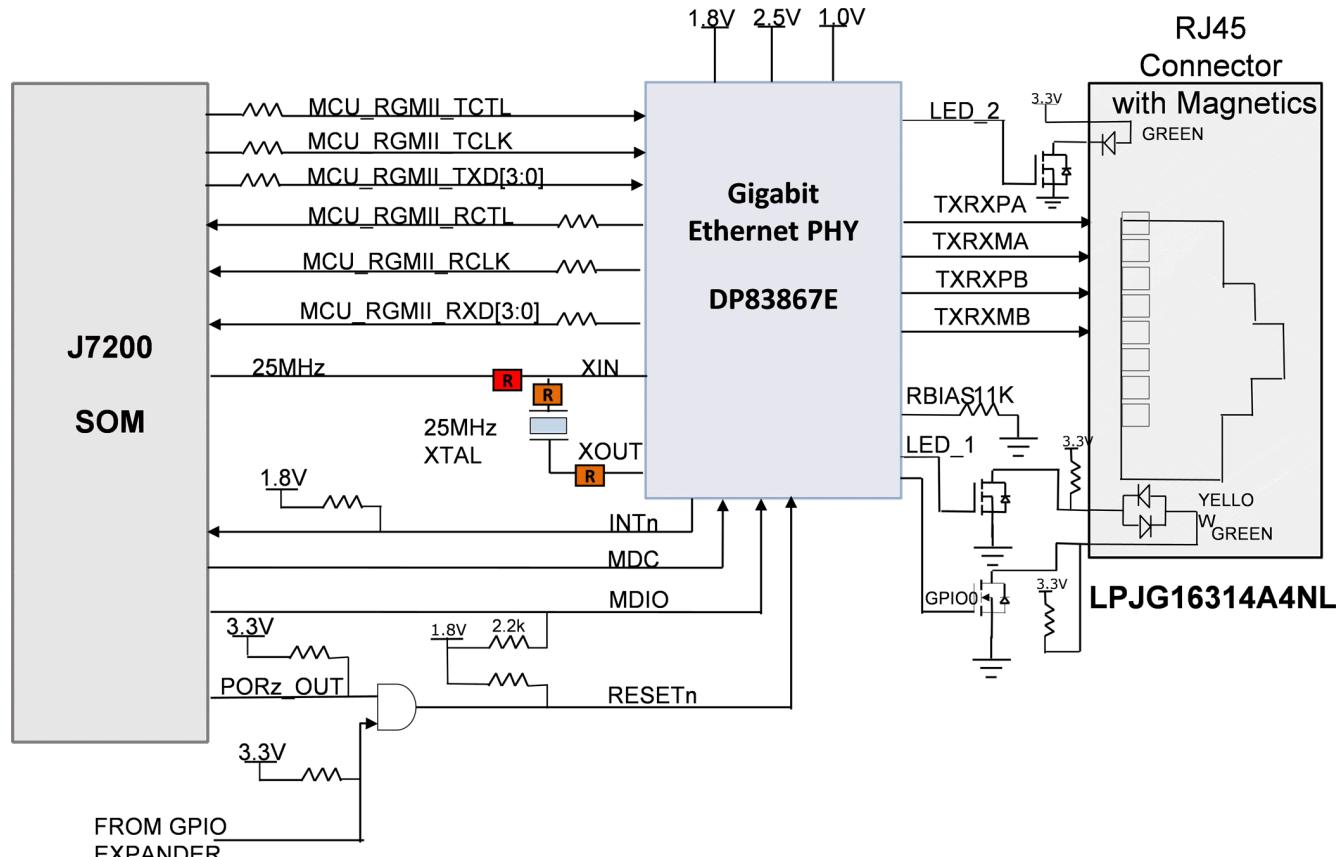
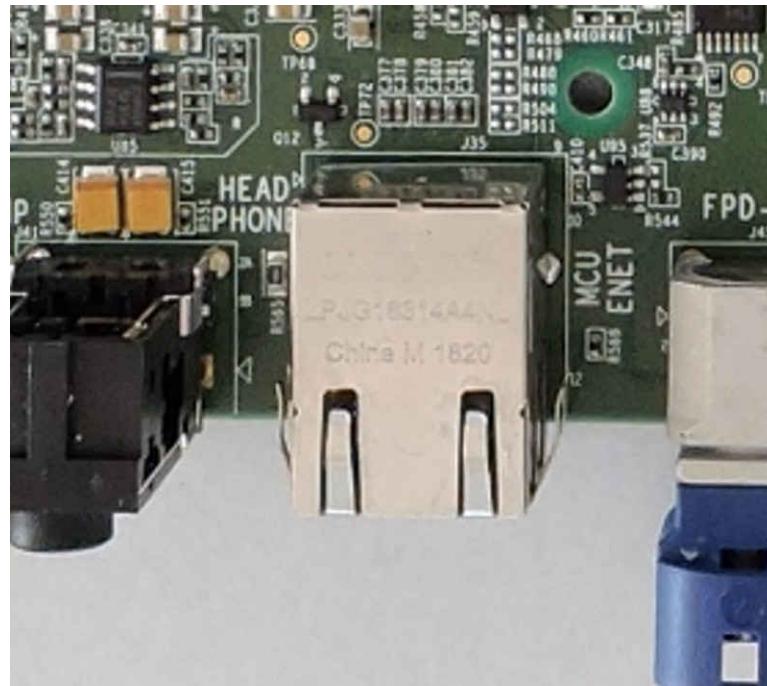


Figure 4-15. MCU Gigabit Ethernet Block Diagram

The EVM is configured to 3.3 V IO supply for MCU RGMII PHY IO signals by default.



**Figure 4-16. Ethernet Interface-MCU Domain**

#### 4.9.1 Gigabit Ethernet PHY Default Configuration

The default configuration of the DP83867 is determined using a number of resistor pull-up and pull-down values on specific pins of the PHY. Depending on the values installed each of the configuration pins can be set to one of four modes by using the pull up and pull down options provided. The EVM uses the 48-pin QFN package, designated with the RGZ suffix, which supports only RGMII interface.

The DP83867 PHY uses four level configurations based on resistor strapping which generate four distinct voltages ranges. The resistors are connected to the RX data and control pins that are normally driven by the PHY and are inputs to the processor.

These are the defaults set for the MCU RGMII:

PHY ADDR: 00000

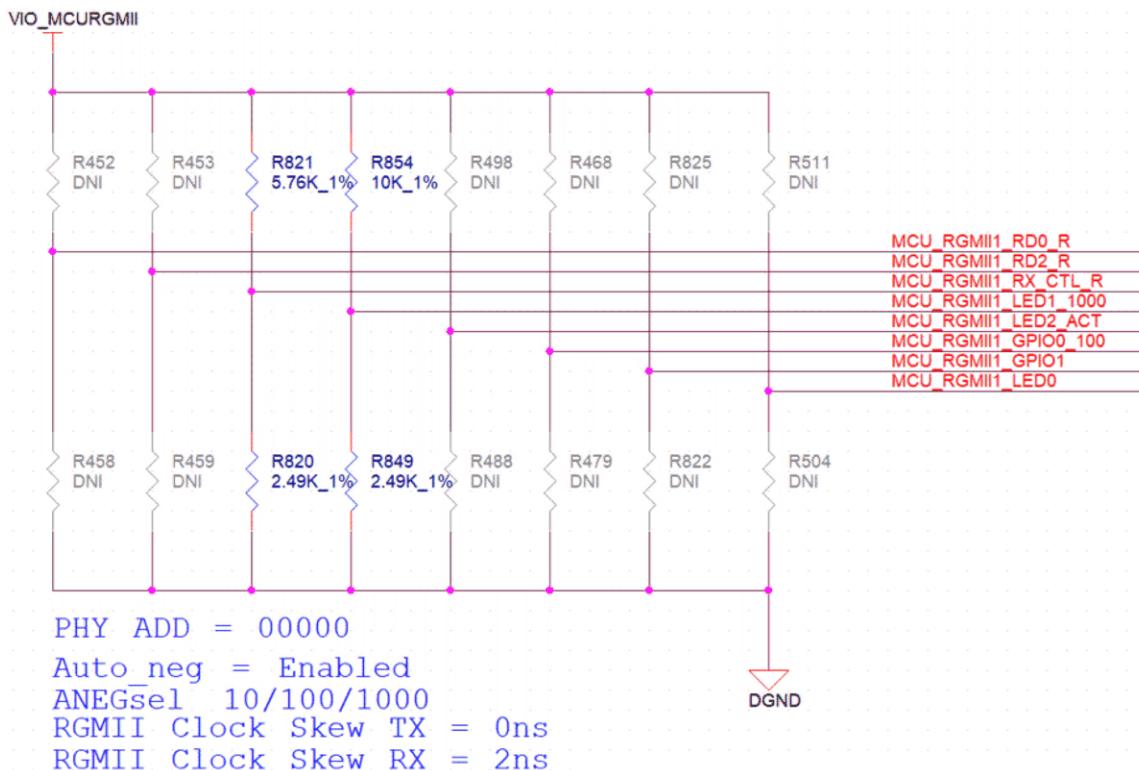
Auto\_neg: Enabled

ANGsel 10/100/1000

RGMII Clk skew Tx: 0 ns

RGMII Clk skew Rx: 2 ns

The strapping resistors are shown in [Figure 4-17](#).



**Figure 4-17. MCU Ethernet PHY Settings**

#### 4.10 QSGMII Ethernet Interface

The SERDES0 SGMII1 signals of J7200 SoC is interfaced to Quad SGMII PHY VSC8514XMK-11 on the Quad Port Ethernet board through CP board, two stacked RJ45 connectors with integrated magnetics PN# LPJG17512AONL used for external communication.

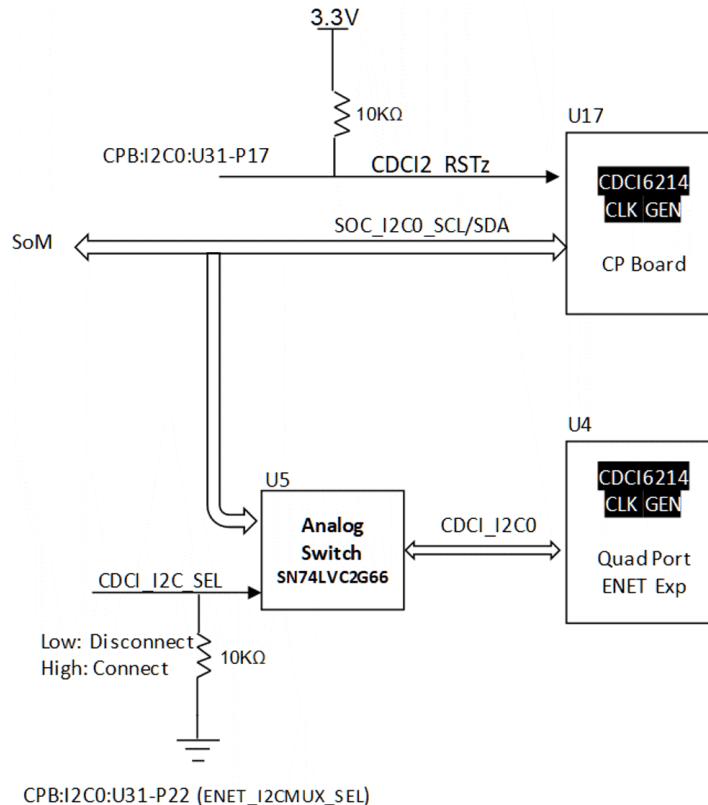
The VC8514 device includes three external PHY address pins, PHYADD [4:2] to allow control of multiple PHY devices on a system board sharing a common management bus. These pins set the most significant bits of the PHY address port map. The lower two bits of the address for each port are derived from the physical address of the port (0 to 3) and the setting of the PHY address reversal bit in register 20E1, bit 9.

Reference clock 156.25 MHz to the PHY is generated from SERDES clock generator (CDCI2) on the CP board by default. Optionally, clock generator on the Quad Port Ethernet board also can provide the clock to the PHY with resistor option.

**Table 4-14. Clock Source Selection**

Clock Source	Install	Remove
From CP Board (Default)	R1, R2	R3, R4
From On board clock generator	R3, R4	R1, R2

If using the alternate clock source for reference, the programming of the clock generate is done through I2C0 port of the SoC. I2C signals to the on board clock generator is connected through an active switch and paths are disconnected by pulling the CDCI\_I2C\_SEL signal low. Since, both on board and CP board clock generator has same I2C slave address, programming of these clock generator needs special attention. While programming on board clock generator, the clock generator (CDCI2) on the common processor boards needs to be under reset.



**Figure 4-18. Quad-SGMII Board I2C**

Coupling capacitors (0.1  $\mu$ F) added in series at the respective driver ends on the QSGMII data signals.

Below are the address and clock configurations:

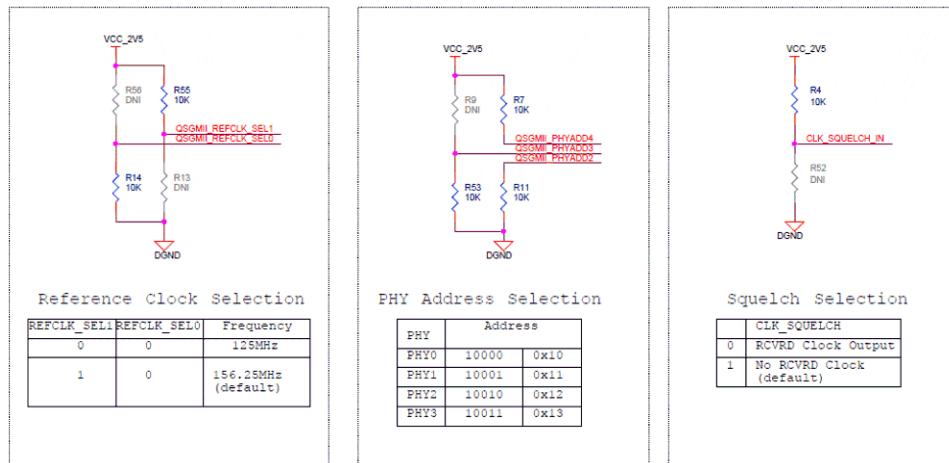
PHY0: 10000 0X10

PHY1: 10001 0X11

PHY2: 10010 0X12

PHY3: 10011 0X13

The resistor strapping options are shown in [Figure 4-19](#).



**Figure 4-19. QSGMII Ethernet PHY Settings**

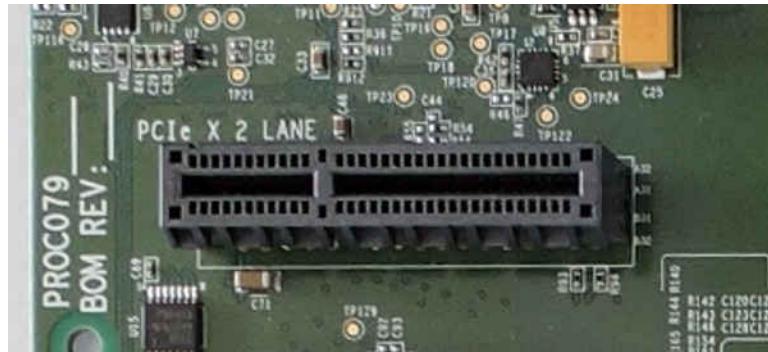
## 4.11 PCIe Interface

The Common processor board is supporting two X4 lane (only one x2L interface is supported in VCL), PCIe connector to accept PCIe form factor daughter card and support PCIe Gen4 operation.

### 4.11.1 X2 Lane PCIe Interface

The x2 lane PCIe interface includes one x4 lane PCIe connector of part number Amphenol 10142333-10111MLF, which supports PCIe Gen4 operation. The pin-out of the connector follows PCIe standard.

The SERDES0 port of J7 SoC is connected to x2 lane PCIe socket for data transfer. PCIe1, USB0\_SS and SGMII3, 4 interfaces are pim muxed with this SERDES0 port.



**Figure 4-20. PCIe Interface SERDES0**

I2C0 from SoC is used for control purpose and is connected to SMBUS on the connector through I2C switch. The link activation signal (INT#) from both the X1 and X2 lane PCIe connectors is terminated to I2C switch.

**Reset:** A dip Switch (SW3) is provided to select the reset source for Root Complex and End-point PCIe operation.

In case of RC mode, signal from GPIO Expander and PORz signals from SoC are ANDed and the output is connected to PCIe connector. The GPIO signal is pulled low to ensure PCIe Reset (#PERST) remains asserted until SoC releases reset.

Whereas, in case of PCIe end point operation, the CP board receives reset signal from the PCIe card.

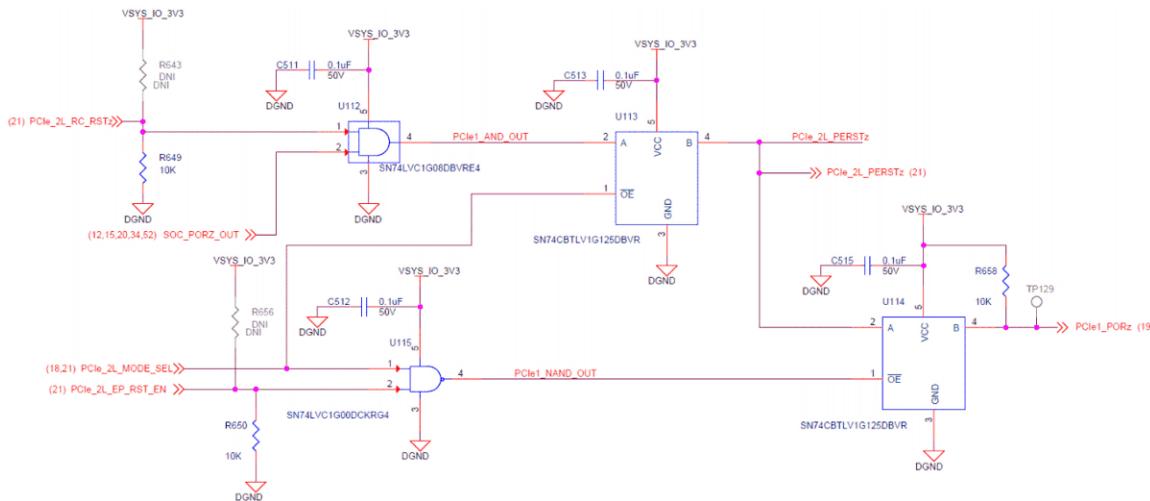


Figure 4-21. 2L-PCIe Root Complex/Endpoint Selection Circuit

**Clock:** A clock generator (CDCI #1) is provided to drive 100MHz HCSL clock for PCIe add on cards and J7200 SoC. Resistor options are provided to select the clock source for host and end point operation.

For PCIe RC operation:

- The add on cards can have clocks driven by SOC or clock generator. Selection can be made through resistors as shown in [Table 4-15](#).

Table 4-15. Reference Clock Selection for PCIe Host Operation

Clock Selected	Mount	Unmount
Reference Clock for SOC from clock generator	R214	R211, C44
	R213	R210, C51
Reference Clock for PCIe connector from SOC	R211, C44	R214, R54
	R210, C51	R213, R56
Reference Clock for PCIe connector from clock generator	R54	R211, C44
	R56	R210, C51

For PCIe Endpoint operation:

- The SOC can have the clock driven by add on cards or clock generator. Selection can be made through resistors as shown in [Table 4-16](#).

Table 4-16. Reference Clock Selection for PCIe Endpoint Operation

Clock Selected	Mount	Unmount
Reference clock for SOC from clock generator	R214	R211, C44
	R213	R210, C51
Reference clock for SOC from PCIe connector	R211, C44	R214, R54
	R210, C51	R213, R56

Hot plug: The PRSNT1# and PRSNT2# signals are the hot plug presence detect signals. The PRSNT1# is pulled up and PRSNT2# is connected to GPIO expander, so that PRSNT1# will be pulled low when a add on card is plugged in as both the PRSNT signals in add on cards will be shorted. Optional resistor is provided to short the PRSNT1# and PRSNT2# to support host and device mode

- For choosing Host or device operation of PCIe card, following resistors must be mounted/unmounted as mentioned in [Table 4-17](#).

**Table 4-17. Resistors for Selecting PCIe Card Host or Device Operation**

Mode	Mount	Demount
Host mode	R631	R630
	R638	
Device mode	R630	R631
	R638	

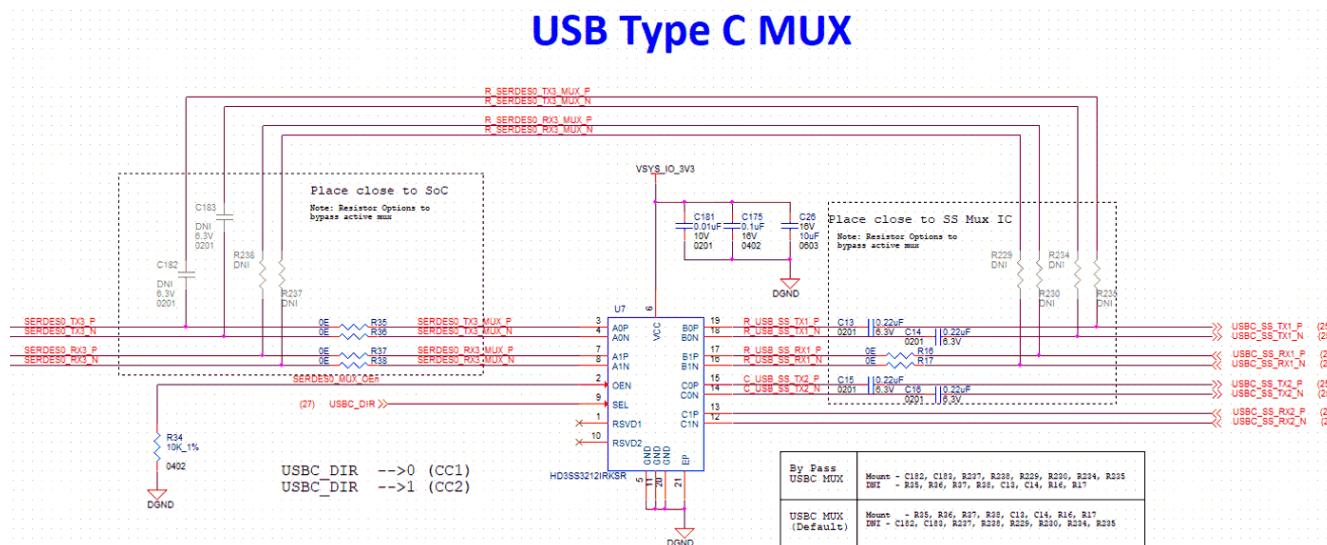
## 4.12 USB Interface

The Common Processor Board includes the following USB interfaces.

- One USB 3.1 Type C interface using TUSB321RWBR and PTPS25830QWRHBTQ1 PD controller
- Four USB 2.0 Interfaces using USB Hub (TUSB4041IPAPR)
- (Not supported in J7200 SoC) One USB 3.0 Micro AB connector. It is reserved for future J7 family devices
- J7200 EVM only supports single USB interface, so the USB3.1 and USB2.0 cannot be supported simultaneously

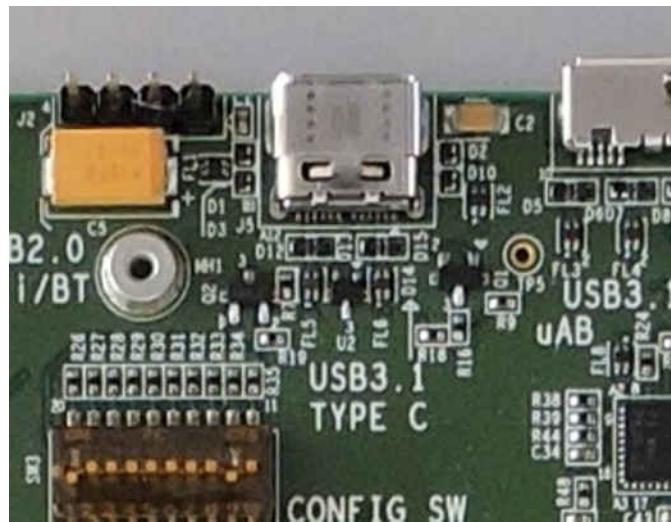
### 4.12.1 USB 3.1 Interface

USB Super speed signals from SERDES0 port of J7200 SoC are connected to USB Type C connector (2012670005). A high speed 1:2 Mux HD3SS3212IRKSR is used to support USB Type C lower and upper ports and the mux is enabled by USBC\_DIR signal from CC controller.



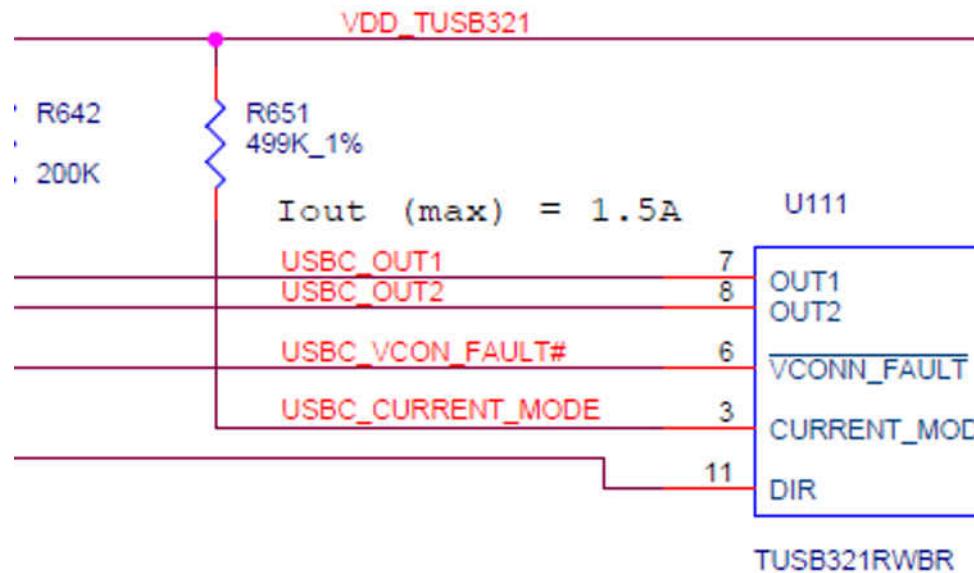
**Figure 4-22. USB SS Mux Circuit**

A CC and PD controller Mfr. Part# TUSB321RWBR and PTPS25830QWRHBTQ1 are used for CC detect, Port mapping and power delivery. This CC controller supports Dual Role Port (DRP), Downstream Facing Port (DFP) and Upstream Facing Port (UFP) modes, In CP board DRP, DFP and UFP modes can be selected through an EVM Configuration dip switch (SW3). The Dip switch settings are given in Table 6.



**Figure 4-23. USB3.1 Type C Interface**

The AC coupling capacitors are provided on TX lines of Super speed signals, and common mode filters (MCZ1210DH900L2TA0G) are used at all the differential pairs. ESD protection diodes are provided on all required USB Signals (TPD1E05U06DPY for super speed signals and TPD2E2U06-Q1 for CC pins). TUSB321's Current Mode pin is pulled high through 499K resistor to set the Maximum Current Iout to 1.5A.



**Figure 4-24. USB3.1 Type C Power Delivery Current Settings**

The control signals for Powerdown and VBUS enable are given from I2C GPIO Expander2 (I2C add: 0x22 - P03) and the SoC DRVVBUS, respectively.

#### 4.12.2 USB 2.0 Interface

The USB0 port of J7200 SoC is used for USB 2.0 interface in J7200 EVM. The USB1 signals are connected to upstream port of USB 2.0 Hub (TUSB4041IPAPR). The four downstream ports from USB.

Hub are connected are shown below:

- Two USB ports are terminated to Type A Stacked Connector (AU-Y1008-2)
- One USB port is connected to 4 Pin Header (PCIe Card - Wi-Fi®/BT)
- One USB port is connected to EVM Expansion connector

The USB0 2.0 signals from J7200 SoC uses 1:2 mux ICs TS3USB221ARSER (for data signals) and SN74CB3Q3257PWR (for control signals) to support both USB0 Type C and USB 2.0 Hub.

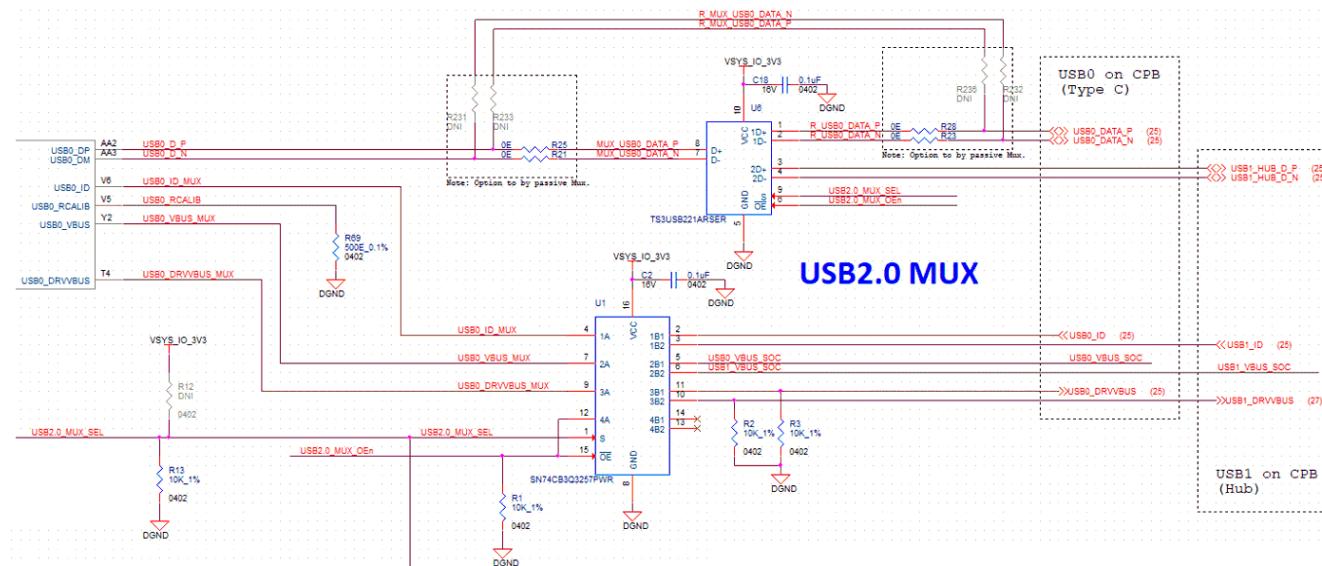


Figure 4-25. USB2.0 MUX Circuit

The reference clock to the USB HUB is provided using 24 MHz crystal and also an optional clock input from the Peripheral clock generator using a resistor mux. The default clock source is set to crystal.

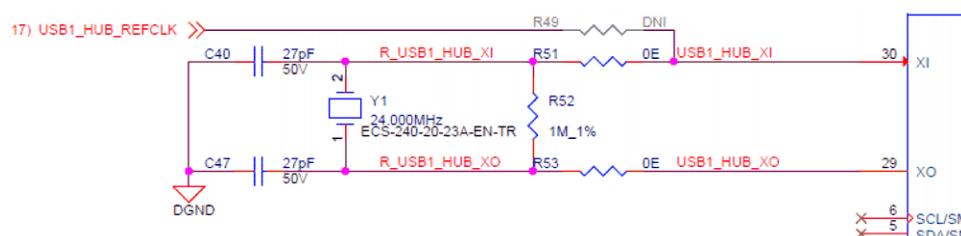
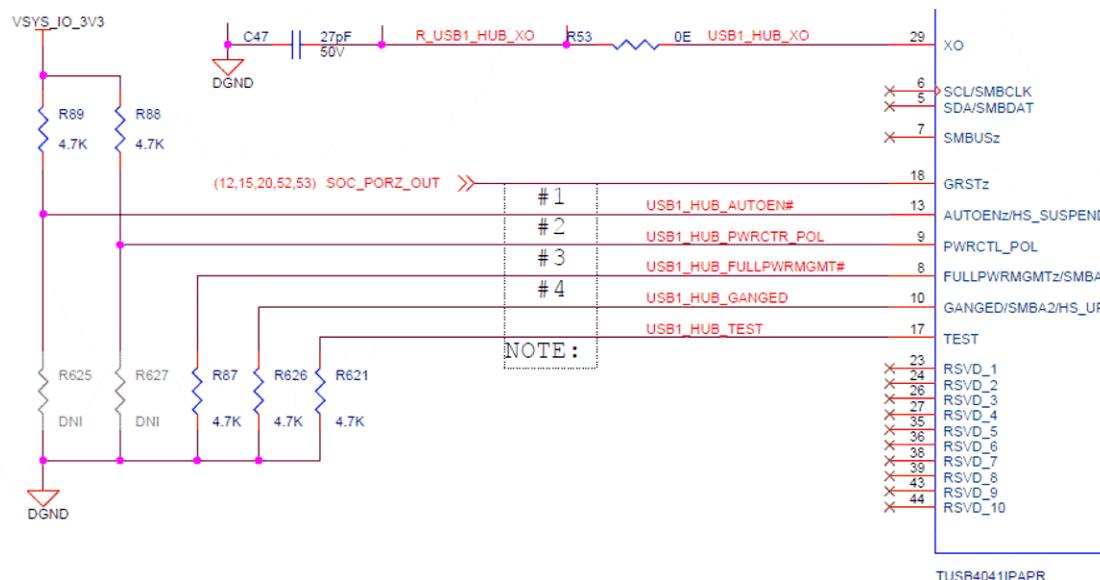


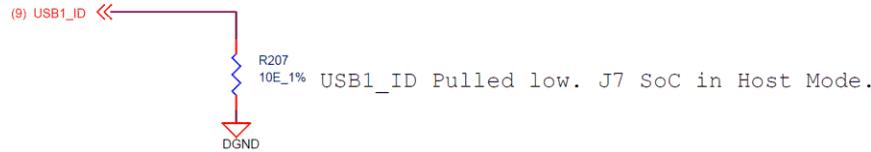
Figure 4-26. USB Hub Reference Clock Circuit

The USB HUB strapping options are provided in [Figure 4-27](#).



**Figure 4-27. USB Hub Settings Circuit**

And, the USB ID pin is pulled low to operate the J7 SoC in Host mode.



**Figure 4-28. USB1 ID Setting for HUB**

#### 4.12.2.1 To PCIe Card Wi-Fi/BT

The downstream port1 of USB HUB is connected to the Wi-Fi/BT header (J2) on the CP board. The power to the Wi-Fi header is provided through current limit load switch with integrated ESD protection device TPD3S014DBVR. The power is controlled by USB hub power enable signal USB1\_DN1\_PE.

The downstreams port 2 and 3 of USB HUB is connected to the stacked USB 2.0 Type-A receptacle AU-Y1008-2 on the CP board. The power to the USB Type-A receptacle is provided through current limit load switch with integrated ESD protection device TPD3S014DBVR for each port. The power is controlled by USB hub power enable signals USB1\_DN2\_PE and USB1\_DN3\_PE.

#### 4.12.2.2 To Expansion Connector

The downstream port4 of USB HUB is connected to EVM Expansion connector. The current version of EVM is not supporting any peripherals on this port. It is reserved for future development.

#### 4.12.3 USB 3.0 Micro AB Interface (Reserved Port)

This is an optional interface provided for a future version of the J7 SoC only; it is not supported in the J7200 EVM.

## 4.13 Audio Interface

Common Processor Board supports TI's Audio Codec IC Mfr. Part# PCM3168APAP, to interface with J7200 SoC McASP Port 0. A 1:3 De-Mux (Mfr. Part# SN74CBT16214CDGGR) Port B1 is used to interface McASP port 0 with codec. Port Selection is controlled by a I2C GPIO Expander and EVM Configuration switch. The mux table is shown in [Table 4-18](#).

**Table 4-18. 1:3 Mux Truth Table for MCASP/TRACE Selection**

MUX_SEL2	MUX_SEL1	MUX_SEL0	FUNCTION
HIGH	HIGH	LOW	A port0 = B1 port
HIGH	HIGH	HIGH	A port0 = B2 port (default)
HIGH	LOW	HIGH	A port0 = B3 port

Port B1: McASP0

Port B2: TRACE

Port B3: LIN/MCAN

The Reference clock (SCKI) to the codec device is sourced from processor's AUDIO\_EXT\_REFCLK2 using 1 to 2 Fan out clock buffer SN74LVC2G125DCUR, the secondary output clock from the fan out buffer is routed to EVM expansion connector to interface to Infotainment Audio Codec devices.

The MODE pin is held LOW to select I2C as control interface. Codec is configured over I2C1 interface. Default I2C address is set to 0x44. The device reset is controlled by the I2C GPIO expander using a I2C1 master port.

### 4.13.1 Line IN Port

Single ended Stereo 1x Line Input signal from the Audio Jack **J38** is converted to differential using "single ended to differential converter with Anti-aliasing low pass filter" and interfaced with CODEC.

### 4.13.2 MIC Input Port

Single ended Stereo 2x MIC Input signals from the stacked Audio Jack **J39** is converted to differential using "single ended to differential converter with Anti-aliasing low pass filter" and interfaced with CODEC. Pre-Amplifier circuit is provider inline to LPF circuit to amplify the external microphone inputs.

Microphone Input ports can be configured for Active and Passive microphones and also can be configured for Line Input. The configuration is set by the resistor option as shown in [Table 4-19](#).

**Table 4-19. Mic Configuration Table**

		Install	Remove
Passive-Mic (default)	BIAS + PREAMP	R2, R3, R5, R6	R1, R4
Active Mic	BIAS ONLY	R1, R2, R3, R5	R3, R6
Line-Input	No BIAS/PREAMP	R1, R4	R2,R3,R5,R6

#### Note

The Reference Rx provided in the above table denotes the text provided in schematics.

### 4.13.3 Line Out Port

2x digital Outputs from the CODEC is converted to single ended and terminated to stereo Audio jack **J40** bottom port using "differential to single ended" converter Line out circuit.

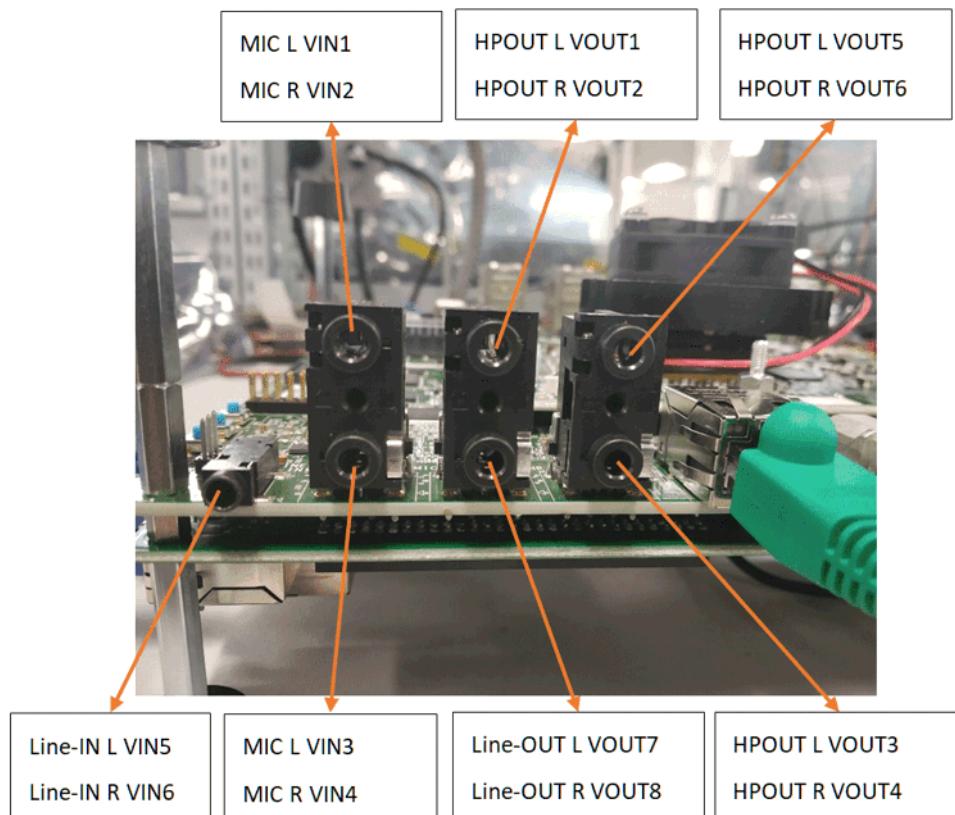
### 4.13.4 Head Phone Port

6x differential digital Outputs from the CODEC is converted to single ended and terminated to stereo Audio Jack **J40** top port and stacked audio jack **J41** with a head phone circuit.

#### 4.13.5 Port Mapping

Common Processor board audio ports are mapped as below.

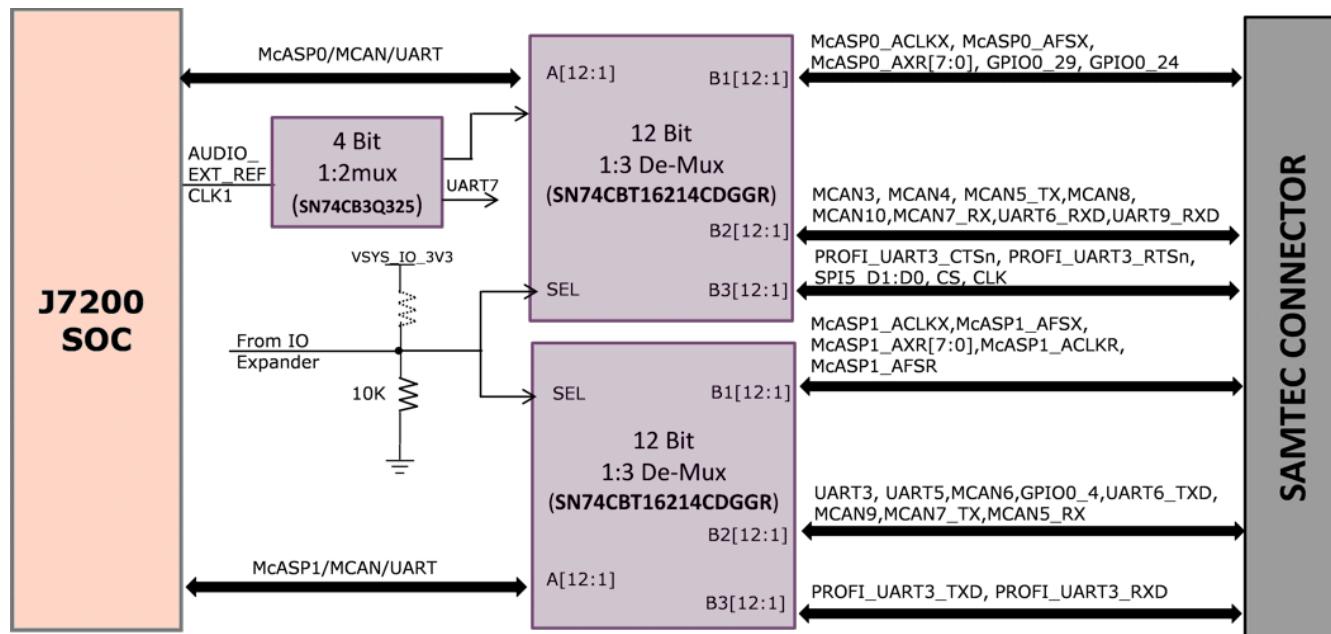
- 3x Standard 3.5mm stacked Stereo Audio Jack Mfr. Part# STX-4235-3/3-N is provided for:
  - 2x – MIC IN, 1x – Line OUT and 3x – Head Phone OUT.
- 1x Standard 3.5mm Stereo Audio Jack Mfr. Part# SJ-3524-SMT-TR provided for:
  - 1x – Line IN interface.



**Figure 4-29. Audio Port Interface Assignment**

McASP0 and McASP1 of J7200 SoC is muxed with UART and MCAN interface. J7200 SOM includes two 1:3 De-Mux (Mfr. Part# SN74CBTLV16292GR) to support Audio codec and Trace functions on the CP Board and MCAN/LIN on the J7x GESI Expansion board. Default channel selection will be done for McASP/TRACE interface through Resistor strap and GPIO from GPIO expander on the J7200 SoC will change the configuration.

AUDIO\_EXT\_REF\_CLK1 of J7200 SoC is used for System Reference clock input of the Audio codec. 4bit 1:2 mux IC is used to route the clock input to the McASP/MCAN mux as shown in [Figure 4-30](#).



**Figure 4-30. McASP/TRACE/MCAN Mux Circuit**

**Table 4-20. 1:3 Mux Truth Table for MCASP/TRACE/MCAN Selection**

MUX_SEL2	MUX_SEL1	MUX_SEL0	FUNCTION
HIGH	HIGH	LOW	A port0 = B1 port
HIGH	HIGH	HIGH	A port0 = B2 port (default)
HIGH	LOW	HIGH	A port0 = B3 port

Port B1: McASP0/1 and TRACE

Port B2: MCAN/UART

Port B3: PROFI\_UART/SPI

#### 4.14 CAN Interface

The four CAN ports of J7200 SoC (MCU\_MCAN0, MCU\_MCAN1, MCAN0 and MCAN3) is supported, three on the Common Processor board and one on the SOM board as explained below.

#### 4.14.1 MCU CAN0

The MCU CAN0 port of J7200 SoC is connected to the CAN transceiver with Wake function supported device TCAN1043-Q1. A 2-pin header **J29** (68002-202HLF) is provided inline for user probe option.

The output of the CAN transceiver is terminated to a 4-pin header **J30** (61300411121).

The signals **MCU\_MCAN0\_H** and **MCU\_MCAN0\_L** are routed as differential signals with 120E impedance with split termination. This Split termination improves the electromagnetic emissions behavior of the network by eliminating fluctuations in the bus common-mode voltages at the start and end of message transmissions.

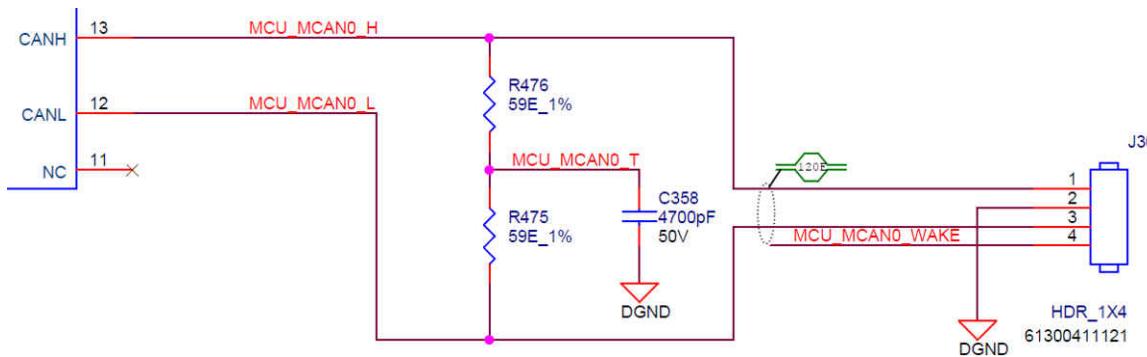


Figure 4-31. MCU CAN0 Interface

VSYS\_MCU\_5V0 to the CAN transceiver is generated using a Step-Up converter TPS61240DRV by giving VSYS\_3V3 as input supply to the converter.

The STB signal is an active low signal held low with integrated pull down by default.

Hardware WAKEn input for the CAN interface is provided using a push-button SW12 available on the Common processor board bottom left corner. However, the MCU\_CAN0 wake feature is disabled by default (resistor population). Only CAN wake-up supported is from MAIN domain.

#### 4.14.2 MCU CAN1

The MCU CAN1 port of J7200 SoC is connected to the CAN transceiver Mfr. Part# TCAN1042HGVD. A 2-pin header **J34** (68002-202HLF) is provided inline for user probe option. This port does not support WAKE function. The signals **MCU\_MCAN1\_H** and **MCU\_MCAN1\_L** are terminated to a 3-pin header **J31** (FCI: 68001-403HLF) with 120E split termination.

The STB signal is an active High signal held high with external pull up by default. The GPIO control from MCU domain provided to pull the line low.

#### 4.14.3 MAIN CAN3 (supports WAKE function)

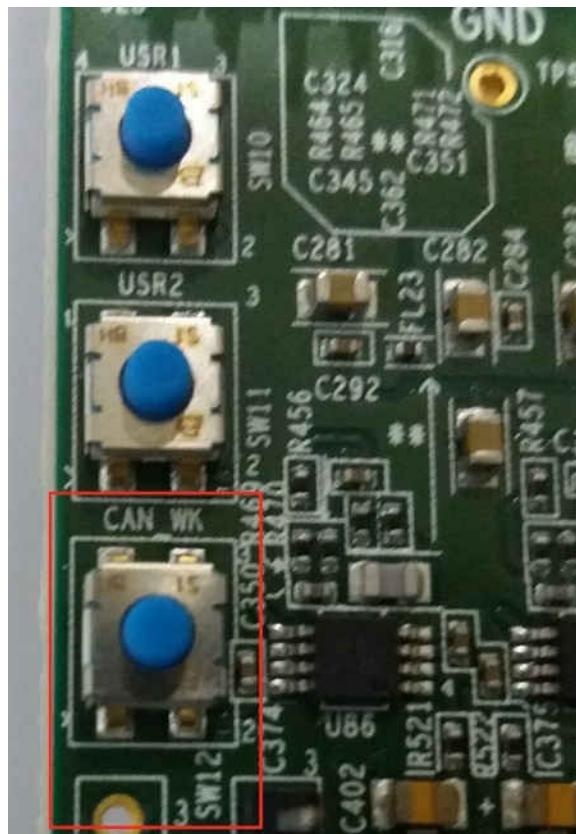
The MAIN CAN3 port of J7200 SoC is connected to the CAN transceiver with Wake function supported device TCAN1043-Q1 using 1:3 mux on the J7200 SoM. The selection of Mux channel will be done using A 2-pin header **J24** (68002-202HLF) is provided inline for user probe option.

The output of the CAN transceiver is terminated to a 4-pin header **J27** (61300411121).

The CAN High/Low signals are routed as differential signals with 120E impedance with split termination. The STB signal is an active low signal held low with integrated pull down by default.

The VCC supply (5 V) to the transceiver is derived from a Step-Up converter.

Hardware WAKEn input for the CAN interface is provided using a push-button SW12.



**Figure 4-32. CAN Wake Push Button**

The CAN Wake signals of both MCU CAN0 and MAIN CAN0 transceivers are tied together and limited the voltage level to 1.8 V using a Zener diode and terminated to SOM -CP B2B connector.

#### 4.14.4 MAIN CAN0

The MCAN0 port of J7200 SoC is connected to support CAN Retention wake function on J7200 SoM board with CAN transceiver Mfr. Part# TCAN1042HGVD. The signals MCAN0\_H and MCAN0\_L are terminated to a 3-pin header **J1** (68001-403HLF) with 120E split termination. The STB signal is an active High signal held high with external pull down by default. The VCC supply (5V) to the transceiver is derived from a Step-Up converter with Mfr. Part# TPS61240DRV. EN\_GPIORET\_LDSW signal is used to enable the boost regulator.

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**Note**

The CAN Transceiver (U75) on the CPB is not supported by J7200 SoM.

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## 4.15 FPD Interface (Audio Deserializer)

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### Note

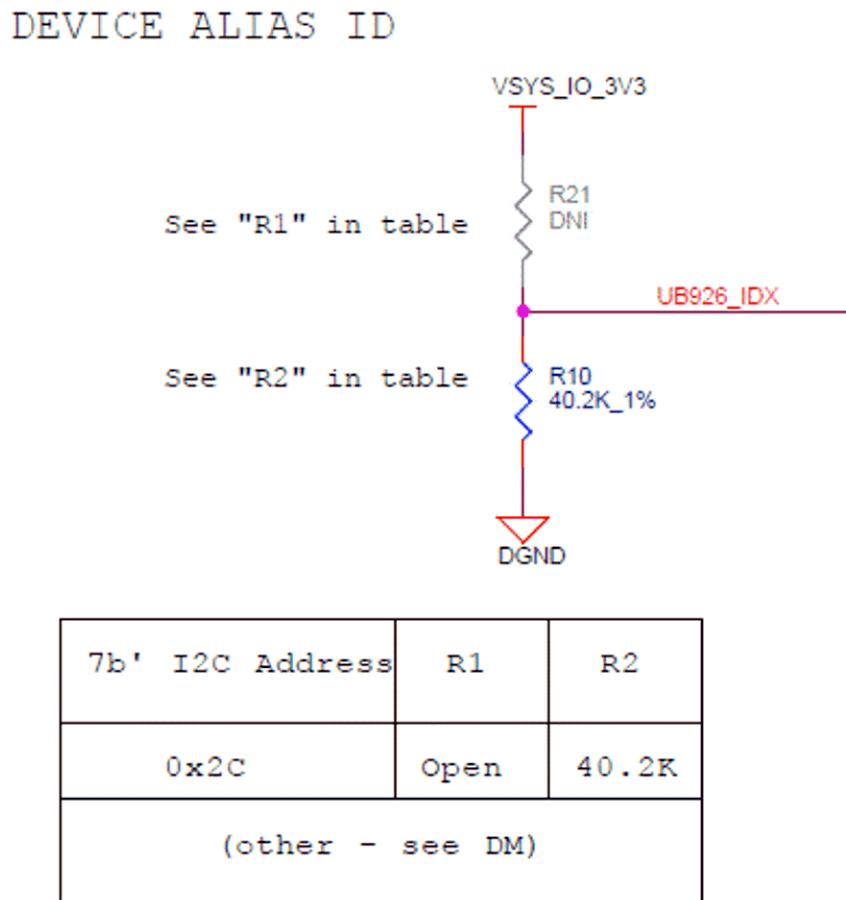
FPD (Audio) Interface on CP board is not supported by J7200 EVM.

---

CP Board supports TI's FPD Link III De-serializer IC Mfr. Part# DS90UB926QSQE for recover the audio signals from Tuner interface using HSD connector Mfr. Part# D4S20G-400A5-C. The de-serializer will recover up to eight digital audio channels plus I2C channel across digital link.

This audio signal is connected to McASP1 port of J7200 SoC through 1:3 DEMUX (SN74CBT16214CDGGR). The channel selection is supported by both GPIO expander and EVM configuration DIP switch (SW3).

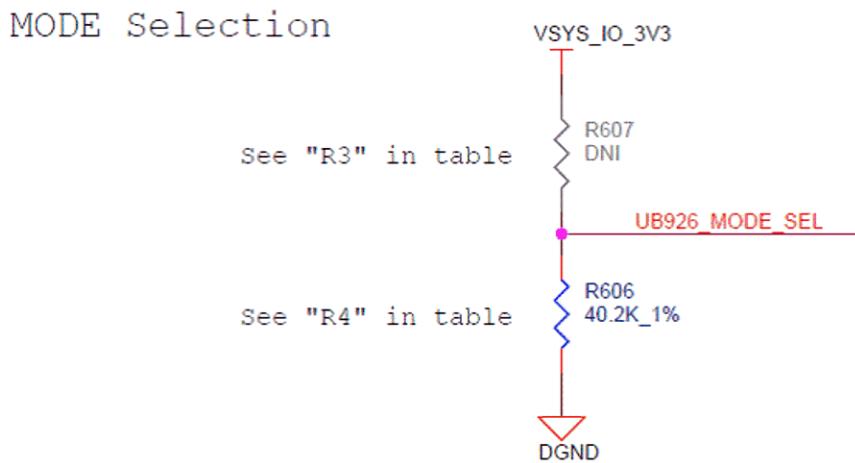
The I2C1 signals of J7200 being used for controlling of the De-serializer. A 40.2KΩ pull down is provided on ID[X] pin to set the 7'b I2C address to 0x2C.



**Figure 4-33. FPD-Link UB926 ID Setting Circuit**

Power +12V is provided to the HSD connector using a power switch TPS1H100AQPWPRQ1 to power the FPD Link-III Tuner expansion board. The power switch is controlled by a GPIO expander signal (UB926\_PWR\_SW\_CNTRL).

The mode selection for the de-serializer is shown in [Figure 4-34](#).



Selected Mode: 0 (Default)	Software Config Only
LFMODE (15 - <85 MHz) REPEATER (OFF) BACK-COMPATIBLE (OFF) I2S-B OFF. 24B RGB	LFMODE (15 - <85 MHz) REPEATER (OFF) BACK-COMPATIBLE (OFF) I2S-B ON. 18B RGB
R3 = <open> R4 = 40.2K, 1% (or any)	R3 = <open> R4 = 40.2K, 1% (or any)

**Figure 4-34. FPD-Link UB926 Mode Selection Circuit**

The pin out for HSD connector **J1** is given in [Table 4-21](#).

**Table 4-21. FPD Audio Deserializer HSD Connector Pinout**

Pin No.	Signal
1	GND
2	RIN_N
3	POWER (12V)
4	RIN_P

## 4.16 I3C Interface

### 4.16.1 Gyroscope

The J7200 SoM has 3D digital accelerometer and 3D gyroscope of Mfr. Part LSM6DSOX. The sensor is controlled SoC MCU I3C lines. The CS pin is pulled high using 10K resistor to support I2C/MIPI I3C mode of operation. The interrupt pins are INT1 and INT2, INT1 is optionally connected to SoC WKUP\_GPIO pin and INT2 is terminated to a test point. 3V3 voltage is connected to IO lines and 1V8 for core.

### MCU I3C

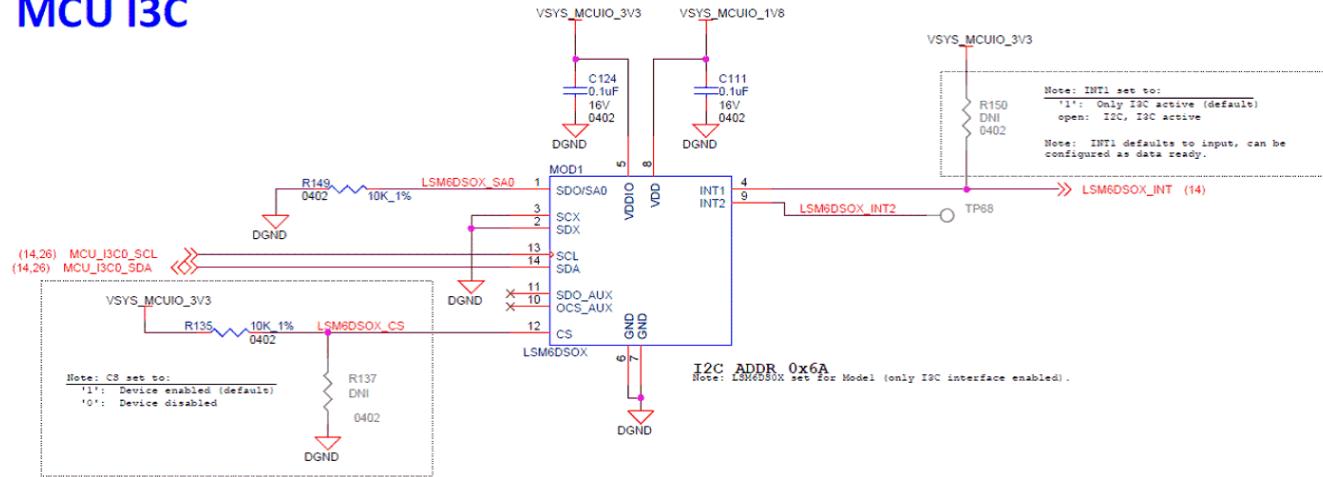


Figure 4-35. 3D Accelerometer and Gyroscope Sensor Circuit

### 4.16.2 I3C Header

Common Processor board supports two I3C headers to validate the J7200 SoC's MCU and MAIN domain I3C interfaces. Out of Two I3C headers, only the MCU I3C header **J33** is populated on J7200 EVM

MCU\_I3C0\_SDA is pulled through 1K Resistor by signal MCU\_I3C0\_SDAPULLEN from SoC.

MAIN\_I3C0\_SCL and MAIN\_I3C0\_SDA are terminated to the I3C header using 2:1 de-muxer IC U46 on Common Processor board. The signal path is disconnected by default using resistors R192 and R193.

The mux selection is controlled by I2C GPIO Expander2 (I2C ADD# 0x22, I2C0) **Port16**.

I3C Header Pinout is given in [Table 4-22](#).

Table 4-22. MCU I3C Header J33 Pinout

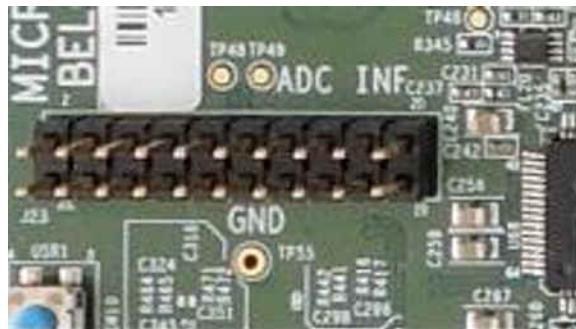
Pin No.	Signal
1	DGND
2	MCU_I3C0_SDA
3	MCU_I3C0_SCL

## 4.17 ADC Interface

### Note

MCU ADC1 port on EVM application board (GESI) is not supported by J7200 EVM.

MCU ADC0 port of J7200 SoC is interfaced to 2x10 header Mfr. Part# TSW-110-07-S-D on Common Processor board. ADC inputs MCU\_ADC0\_AIN[7:0] and external Trigger input MCU\_ADC\_EXT\_TRIGGER0 is connected to J7200 SoC through SOM board. MCU\_ADC0\_REF\_P and MCU\_ADC0\_REF\_N are not routed to J7200 SoC as these signals are tied internally in SoC package.



**Figure 4-36. 3D ADC Interface Connector**

Pin No.	Signal	Pin No.	Signal
1	DGND	2	MCU_ADC0_AIN3
3	MCU_ADC0_AIN7	4	MCU_ADC0_AIN0
5	MCU_ADC0_AIN1	6	MCU_ADC0_AIN6
7	DGND	8	DGND
9	MCU_ADC0_AIN4	10	MCU_ADC0_REF_P
11	MCU_ADC0_AIN2	12	MCU_ADC0_REF_N
13	DGND	14	DGND
15	MCU_ADC0_AIN5	16	MCU_ADC_EXT_TRIGGER0
17	NC	18	NC
19	DGND	20	DGND

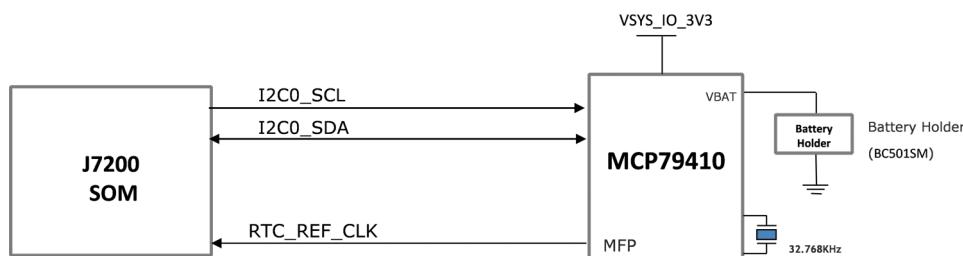
## 4.18 RTC Interface

A real-time clock (RTC) module Mfr. Part# MCP79410-I/SN is connected I2C0 interface of J7200 SoC.

The RTC device is being powered by 3.3 V and a battery holder BC501SM is connected to the VBAT pin as an external battery power option. A 32.768 kHz quartz crystal is used to provide clock for the device.

MFP pin of RTC module is used to generate optional reference clock to the SoC's WKUP\_LFOSC.

7-bit I2C addresses are 0x57 and 0x6F.



**Figure 4-37. RTC Block Diagram**

## 4.19 Apple Authentication Header

The common processor board has a provision to support Apple authentication interface. In J7200 EVM, the Apple authentication board can be interfaced with J7200 SoC in two options: module interface and device interface.

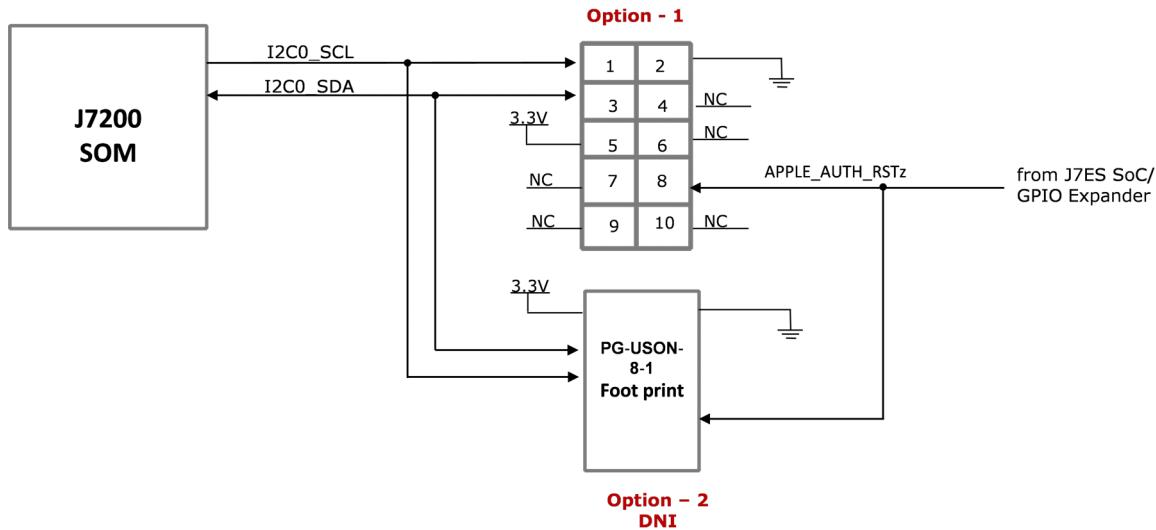


Figure 4-38. Apple Authentication Block Diagram

### 4.19.1 Module Interface

Common Processor board have a 2.54 mm Dual row 10 Pin Receptacle Mfr. Part# 2214BR-10G.

I2C0 Port of J7200 SoC and Reset from GPIO Expander is terminated to this connector. 3.3 V supply is provided to the connector **J9**.

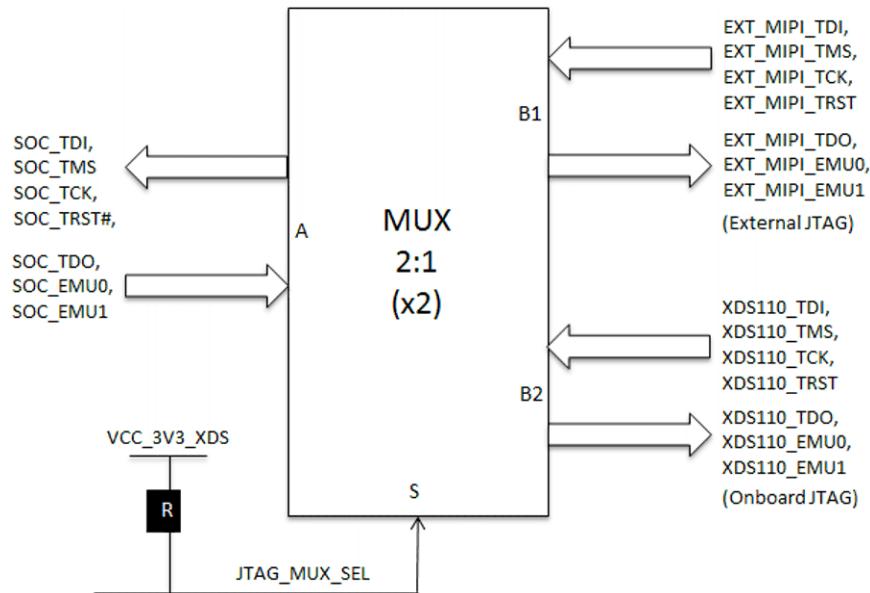
Detailed signal and pin description are given in [Table 4-23](#).

Table 4-23. APPLE AUTH Header J9 Pinout

Pin No.	Signal	Description
1	I2C0_SCL	I2C slave interface, clock connection
3	I2C0_SDA	I2C slave interface, data connection
8	APPLE_AUTH_RSTz	Reset, Active low
5	VSYS_IO_3V3	Power 3.3V
2	DGND	Ground
4,6,7,9,10	NC	Not Connected

## 4.20 JTAG Emulation

The Common processor board includes XDS110 class on board emulation through the micro B connector J3. It also has an option to support external emulation through MIPI 60 pin header. When an external emulator is connected, XDS110 emulation circuitry path will be disconnected automatically.



**Figure 4-39. JTAG Mux**

**Table 4-24. JTAG 1:2 Mux selection**

Condition	MUX_SEL	Function
XDS110 Powered via USB	HIGH	A<->B2 port [On Board EMU]
External Emulator attached	LOW	A<->B1 port [EXTERNAL EMU]

As mentioned, the design includes the footprint for a MIPI 60-pin (J16) connector with connections for JTAG and trace capabilities. The trace pins are multiplexed with other functions (Multichannel Audio Serial Port (McASP0), McASP1, UART and MCAN) uses two on-board mux ICs (U10 and U14) on J7200 SoM to select the different functions. The mux is defaulted to the trace/McASP functions. The 1:3 mux ICs are controlled by bits of the I2C general-purpose input/output (GPIO) expander (I2C add: 0x21; I2C Inst:I2C0) on the J7200 SoM board.

Addition to the J7200 on-board, CPB uses two 1:3 on-board mux ICs (U44 & U121) to support audio and Trace functions. The mux is defaulted to MIPI 60pin connector. The 1:3 mux ICs are controlled by bits of the I2C GPIO expander2 (I2C add: 0x22; I2C Inst:I2C0) on Common Processor board. There is an option to set the state using the DIP switch SW3 Position 2.

**Table 4-25. TI 60 Pin Connector (J16) Pin-Out**

Pin No.	Signal	Pin No.	Signal
1	VSYS_IO_3V3	31	TRC_DATA6
2	MIPI_TMS	32	NC
3	MIPI_TCK	33	TRC_DATA7
4	MIPI_TDO	34	NC
5	MIPI_TDI	35	TRC_DATA8
6	MIPI_TGTRST#	36	NC
7	MIPI_RTCK	37	TRC_DATA9
8	MIPI_TRST_PD (EXT_MIPI_TRST#)	38	EXT_MIPI_EMU0
9	MIPI_nTRSTPU	39	TRC_DATA10

**Table 4-25. TI 60 Pin Connector (J16) Pin-Out (continued)**

Pin No.	Signal	Pin No.	Signal
10	NC	40	EXT_MIPI_EMU1
11	NC	41	TRC_DATA11
12	VSYS_IO_3V3	42	NC
13	TRC_CLK	43	TRC_DATA12
14	NC	44	NC
15	DGND	45	TRC_DATA13
16	DGND	46	NC
17	TRC_CTL	47	TRC_DATA14
18	TRC_DATA19	48	NC
19	TRC_DATA0	49	TRC_DATA15
20	TRC_DATA20	50	NC
21	TRC_DATA1	51	TRC_DATA16
22	TRC_DATA21	52	NC
23	TRC_DATA2	53	TRC_DATA17
24	NC	54	NC
25	TRC_DATA3	55	TRC_DATA18
26	NC	56	NC
27	TRC_DATA4	57	DGND
28	NC	58	JTAG_MUX_SEL
29	TRC_DATA5	59	NC
30	NC	60	NC

The EVM Common processor board Kit includes two JTAG converters, one is to convert MIPI 60 pin to TI14 pin JTAG emulator and the other one is to convert MIPI 60 pin to CTI20 pin JTAG.

[Table 4-26](#) and [Table 4-27](#) shows Pinouts of TI14 pin and CTI 20 pin JTAG converters.

**Table 4-26. cTI20 Pin Connector (J1-Refer PROC081E2 SCH) Pinout**

Pin No.	Signal	Pin No.	Signal
1	MIPI_20_TMS	11	MIPI_20_TCK
2	MIPI_20_TRST	12	DGND
3	MIPI_20_TDI	13	MIPI_20_EMU0
4	MIPI_20_TDIS	14	MIPI_20_EMU1
5	MIPI_20_VTREF	15	SYSRST#
6	NC (key)	16	DGND
7	MIPI_20_TDO	17	NC
8	20PJTAG_DET	18	NC
9	MIPI_20_RTCK	19	NC
10	DGND	20	DGND

**Table 4-27. TI14 Pin Connector (J2-Refer PROC081E2 SCH) Pinout**

Pin No.	Signal	Pin No.	Signal
1	MIPI_14_TMS	8	14PJTAG_DET
2	MIPI_14_TRST	9	MIPI_14_RTCK
3	MIPI_14_TDI	10	DGND
4	MIPI_14_TDIS	11	MIPI_14_TCK
5	MIPI_14_VTREF	12	DGND
6	NC (key)	13	MIPI_14_EMU0

**Table 4-27. TI14 Pin Connector (J2-Refer PROC081E2 SCH) Pinout (continued)**

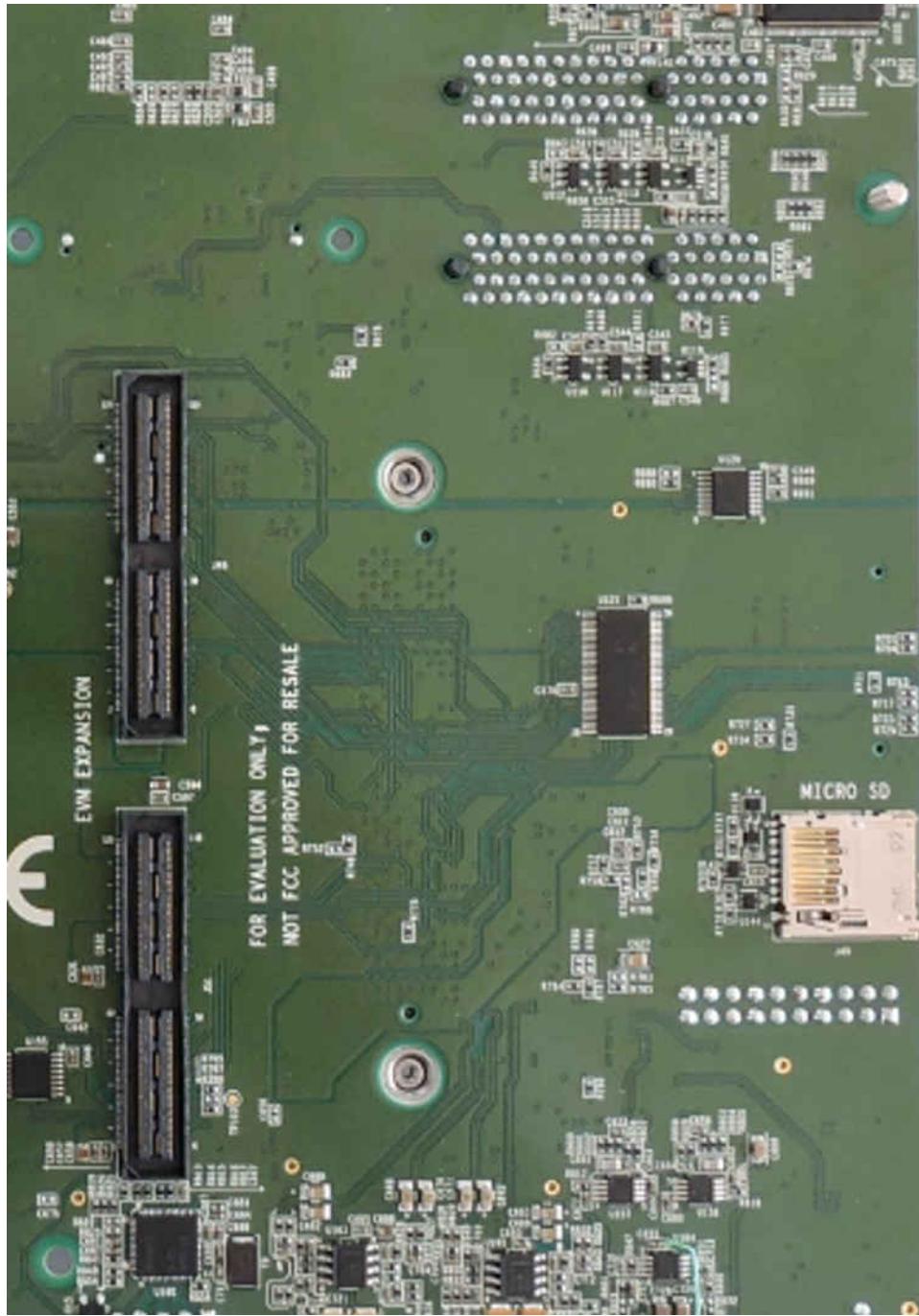
Pin No.	Signal	Pin No.	Signal
7	MIPI_14_TDO	14	MIPI_14_EMU1

## 4.21 EVM Expansion Connectors

The Common processor board includes an Expansion connector of QSH-060-01-L-D-A-K with 5 mm mating height allowing multiple expansion boards (Infotainment or GESI Expansion) to be stacked below the processor board.

The GESI Expansion board can be plugged into EVM expansion connectors (J46 and J51).

Infotainment Expansion board is not supported in J7200 EVM.

**Figure 4-40. Expansion Board Interface Connectors**

The EVM Expansion connectors pinouts are shown in [Table 4-28](#) and [Table 4-29](#).

**Table 4-28. EVM Expansion Connector J46 Pinout**

EVM Expansion Connector Interface J46			
Pin No.	Signal	Pin No	Signal
1	DGND	2	VCC_12V0
3	DGND	4	VCC_12V0
5	DGND	6	VCC_12V0
7	MCASP1_AXR3/PRG0_RGMII2_RXC	8	VOUT0_DATA15/PRG1_RGMII2_TX_CTL
9	PRG0_RGMII2_RD3	10	VOUT0_DATA14/PRG1_RGMII2_TD3
11	MCASP1_AXR2/PRG0_RGMII2_RX_CTL	12	VOUT0_HSYNC/PRG1_RGMII2_TXC
13	MCASP1_AXR0/PRG0_RGMII2_RD0	14	VOUT0_DATA11/PRG1_RGMII2_TD0
15	MCASP1_AXR1/PRG0_RGMII2_RD1	16	VOUT0_DATA13/PRG1_RGMII2_TD2
17	PRG0_RGMII2_RD2	18	VOUT0_DATA12/PRG1_RGMII2_TD1
19	DGND	20	DGND
21	VOUT0_EXTPCLKIN/MCAN6_TX	22	VPFE0_DATA6/MCAN5_TX
23	VOUT0_DATA5/MCAN6_RX	24	VPFE0_DATA7/MCAN5_RX
25	VOUT0_DATA7/MCAN7_TX	26	AUDIO_EXT_REFCLK1/MCAN4_TX
27	VOUT0_DATA8/MCAN7_RX	28	VOUT0_DATA22/MCAN4_RX
29	VOUT0_DATA9/PRG1_UART0_RXD	30	PRG1_UART0_RTS#
31	VOUT0_DATA10/PRG1_UART0_TXD	32	VOUT0_DATA23/SPI6_CS1(PROFI_UART3_CTSn)
33	VOUT0_VSYNC/SPI6_D0	34	VOUT0_DE/SPI6_CLK
35	NC	36	VOUT0_PCLK/SPI6_D1
37	DGND	38	DGND
39	VOUT0_DATA0/PRG1_RGMII2_RD0	40	VOUT0_DATA19/PRG1_RGMII1_TD3
41	VOUT0_DATA2/PRG1_RGMII2_RD2	42	VOUT0_DATA16/PRG1_RGMII1_TD0
43	VOUT0_DATA1/PRG1_RGMII2_RD1	44	VOUT0_DATA20/PRG1_RGMII1_TX_CTL
45	VOUT0_DATA3/PRG1_RGMII2_RD3	46	VOUT0_DATA18/PRG1_RGMII1_TD2
47	VOUT0_DATA4/PRG1_RGMII2_RX_CTL	48	VOUT0_DATA21/PRG1_RGMII1_TXC
49	VOUT0_DATA6/PRG1_RGMII2_RXC	50	VOUT0_DATA17/PRG1_RGMII1_TD1
51	DGND	52	DGND
53	MCASP0_AXR5/MCAN9_TX	54	VPFE0_DATA12/PRG1_MDIO0_MDC
55	MCASP0_AXR6/MCAN9_RX	56	VPFE0_DATA11/PRG1_MDIO0_MDIO
57	MCASP0_ACLKX/SPI3_CS1	58	SPI3_CS0 (MCAN10_TX)
59	MCASP0_AFSX/SPI3_CS2	60	MCASP1_AFSX/MCAN11_RX (MCAN10_RX)
61	McASP0_AXR3 (PROFI_UART_SEL)	62	NC
63	WKUP_I2C0_SDA	64	SOC_PORZ_OUT
65	WKUP_I2C0_SCL	66	PRG0_PWM0_TZ_OUT (PD: GPIO_PRG1_RGMII_RST)
67	DGND	68	DGND
69	MCASP0_AXR0/PRG0_RGMII1_RD0	70	MCASP0_AXR8/PRG0_RGMII1_TD1
71	MCASP0_AXR2/PRG0_RGMII1_RX_CTL	72	MCASP0_AXR7/PRG0_RGMII1_TD0
73	MCASP0_AXR4/PRG0_RGMII1_RXC	74	MCASP0_AXR11/PRG0_RGMII1_TX_CTL
75	PRG0_RGMII1_RD2	76	MCASP0_AXR10/PRG0_RGMII1_TD3
77	MCASP0_AXR1/PRG0_RGMII1_RD1	78	MCASP0_AXR9/PRG0_RGMII1_TD2
79	PRG0_RGMII1_RD3	80	MCASP0_AXR12/PRG0_RGMII1_TXC
81	DGND	82	DGND
83	MCASP1_AXR8/PRG0_RGMII2_TD1	84	MCASP6_ACLKX/PRG1_RGMII1_RD0
85	MCASP1_AXR7/PRG0_RGMII2_TD0	86	MCASP6_AFSR/PRG1_RGMII1_RXC
87	GPIO0_79/PRG0_RGMII2_TXC	88	MCASP6_AFSX/PRG1_RGMII1_RD1

**Table 4-28. EVM Expansion Connector J46 Pinout (continued)**

EVM Expansion Connector Interface J46			
Pin No.	Signal	Pin No	Signal
89	PRG0_RGMII2_TD2	90	PRG1_RGMII1_RD3
91	PRG0_RGMII2_TX_CTL	92	MCASP6_ACLKR/PRG1_RGMII1_RX_CTL
93	MCASP2_AXR0/PRG0_RGMII2_TD3	94	MCASP6_AXR0/PRG1_RGMII1_RD2
95	DGND	96	DGND
97	MDIO0_MDC	98	PRG0_MDIO0_MDC/I2C5_SDA
99	MDIO0_MDIO	100	PRG0_MDIO0_MDIO/I2C5_SCL
101	SPI3_D0	102	MCASP0_AXR13/PRG0_PWM0_B2 (CAN_STB)
103	SPI3_D1	104	NC
105	SPI3_CLK	106	RGMII_REFCLK
107	DGND	108	DGND
109	I2C0_SCL	110	MCASP1_ACLKX (GPIO_LIN_EN)
111	I2C0_SDA	112	SOC_I2C2_SCL
113	I2C1_SCL	114	SOC_I2C2_SDA
115	I2C1_SDA	116	NC
117	NC	118	EXP_RSTz
119	DGND	120	DGND

**Table 4-29. EVM Expansion Connector J51 Pinout**

EVM Expansion Connector Interface J51			
Pin no.	Signal	Pin no.	Signal
1	DGND	2	EXP_3V3
3	DGND	4	EXP_3V3
5	DGND	6	EXP_3V3
7	MCASP1_AXR5/UART8_RXD	8	I2C3_SCL (I2C1_SCL)
9	MCASP1_AXR6/UART8_TXD	10	I2C3_SDA (I2C1_SDA)
11	EQEP0_A	12	EQEP0_I
13	EQEP0_B	14	EQEP0_S
15	GPIO1_23/UART9_RXD (GPIO_RGMII2_INT#)	16	EXP_CODEC_SCKI
17	GPIO1_24/UART9_TXD	18	NC
19	EXP_EEPROM_A0	20	INFO_CAM_VIO_SEL
21	EXP_EEPROM_A1	22	EXP_REFCLK
23	EXP_EEPROM_A2	24	NC
25	BOARDID_EEPROM_WP	26	PRG1_IEP0_EDIO_OUTVALID
27	GPIO0_6	28	PERIPH_RSTz
29	GPIO0_61 (GPIO_RGMII2_RST)	30	RESETSTATz
31	UB926_GPIO2	32	EXP_MUX1
33	UB926_GPIO3	34	EXP_MUX2
35	NC	36	EXP_MUX3
37	NC	38	NC
39	DGND	40	DGND
41	GPMC0_A1	42	GPMC0_A22
43	GPMC0_A2	44	GPMC0_DIR
45	GPMC0_A3	46	GPMC0_A17
47	GPMC0_A4	48	GPMC0_BE1#
49	GPMC0_A5	50	GPMC0_A16
51	GPMC0_A7	52	GPMC0_A21

**Table 4-29. EVM Expansion Connector J51 Pinout (continued)**

EVM Expansion Connector Interface J51			
Pin no.	Signal	Pin no.	Signal
53	GPMC0_A6	54	GPMC0_A15
55	GPMC0_A9	56	GPMC0_A20
57	GPMC0_A11	58	GPMC0_A14
59	GPMC0_A8	60	GPMC0_A18
61	GPMC0_A10	62	GPMC0_A19
63	GPMC0_A12	64	GPMC0_A13
65	NC	66	NC
67	DGND	68	DGND
69	RESERVED_NET5	70	NC
71	NC	72	NC
73	RESERVED_NET13	74	NC
75	NC	76	NC
77	DGND	78	VSYS_5V0
79	DGND	80	VSYS_5V0
81	DGND	82	VSYS_5V0
83	MCU_ADC1_AIN0	84	RESERVED_NET1 (LIN2_UART_RXD)
85	MCU_ADC1_AIN1	86	RESERVED_NET2 (LIN2_UART_TXD)
87	MCU_ADC1_AIN2	88	RESERVED_NET4 (LIN3_UART_RXD)
89	MCU_ADC1_AIN3	90	RESERVED_NET6 (LIN3_UART_TXD)
91	MCU_ADC1_AIN4	92	RESERVED_NET9 (LIN4_UART_RXD)
93	MCU_ADC1_AIN5	94	RESERVED_NET7 (LIN4_UART_TXD)
95	MCU_ADC1_AIN6	96	RESERVED_NET3 (LIN5_UART_RXD)
97	MCU_ADC1_AIN7	98	RESERVED_NET10 (LIN5_UART_TXD)
99	NC	100	VSYS_IO_3V3
101	NC	102	VSYS_IO_3V3
103	MCU_ADC_EXT_TRIGGER1	104	VSYS_IO_3V3
105	DGND	106	NC
107	I2C6_SCL	108	NC
109	I2C6_SDA	110	NC
111	NC	112	NC
113	USB1_DN4_PE	114	VSYS_IO_1V8
115	USB1_DN4_D_N	116	VSYS_IO_1V8
117	USB1_DN4_D_P	118	VSYS_IO_1V8
119	DGND	120	DGND

## 4.22 ENET Expansion Connector

The Common processor board includes an Expansion connector of 171446-1109 with 5mm mating height allowing ENET expansion board (Quad-Port Ethernet Expansion) to be stacked on Top side of the processor board.

This section provides an overview of the different interfaces and circuits on the Quad port Ethernet Expansion Board.

### 4.22.1 Power Requirements

The Expansion Card utilizes power from Common processor board through expansion connector and it has two Low Drop Out circuits to supply Quad Port SGMII PHY with the necessary voltage and the power required.

Test points for each power outputs are provided on the Ethernet Expansion card and are mention in the below Table.

SI No.	Power Supply	Test Point	Voltage	Tolerance
<b>Card Top Side</b>				
1	VCC_12V0	C30.1	12 V	
2	VSYS_5V0	C34.1	5 V	
3	VCC_3V3	C33.1	3.3 V	
4	VCC_2V5	TP2	2.5 V	
5	VCC_1V	TP10	1 V	

### 4.22.2 Clock

#### 4.22.2.1 Main Clock

The Reference clock to the PHY will be generated from TI's Clock Generator Mfr. Part Number# CDCI6214RGET, which is placed on the Common Processor (CPU) Board. Clock inputs are AC coupled and LVDS compliant. The clock generator can be configured by I2C0 of the J7200 SoC. I2C address of this clock generator is 0x77.

#### 4.22.2.2 Optional Clock

Optionally, Reference clock can be supplied by the SERDES clock generator Mfr. Part Number# CDCI6214RGET located on the Quad port Ethernet Expansion Board, which can be configured by I2C0 of the J7200 SOC. The I2C address of this clock generator is 0x77 and this address conflicts with CDCI Chip on Common processor Board. An I2C switch on the Quad port Ethernet Expansion Board is used to remove the address conflict by either connecting any one of the clock generators.

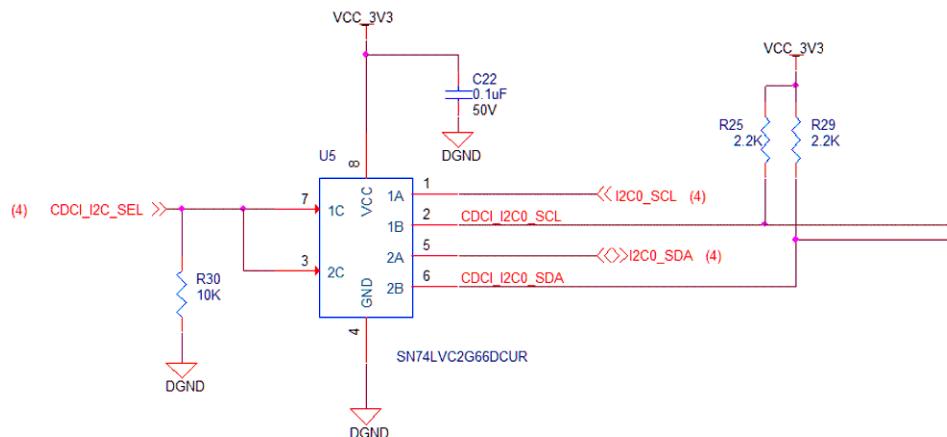


Figure 4-41. CDCI I2C Isolation Circuit

Setting the CDCI\_I2C\_SEL IO EXP bit high will connect the I2C bus to CDCI (for programming) on the Quad Port Ethernet Expansion Board. During this time the CDCI device U17 on the Common Processor board should be in reset mode.

#### 4.22.3 Reset Signals

QSGMII\_RESETz is a reset signal sourced from Common Processor board. This signal is used to reset the QSGMII PHY on the board.

QSGMII\_RESETz is an AND output of SOC\_PORz\_out and ENET\_EXP\_RSTz . The ENET\_EXP\_RSTz signal is asserted by an I2C GPIO Expander2 (I2C ADD# 0x22, I2C0) Port21 in the common processor board.

ENET Expansion connector Pinout is given in [Table 4-30](#).

**Table 4-30. ENET Expansion Connector J10 Pinout**

ENET Expansion Connector Interface J10	
Pin No.	Signal
1	DGND
2	NC
3	NC
4	DGND
5	NC
6	NC
7	DGND
8	NC
9	NC
10	DGND
11	VSYS_IO_3V3
12	VSYS_IO_3V3
13	DGND
14	EEPROM_A0
15	EEPROM_A1
16	EEPROM_A2
17	DGND
18	EEPROM_WP
19	REFCLK_25MHZ
20	DGND
21	WKUP_I2C0_SCL
22	WKUP_I2C0_SDA
23	DGND
24	I2C0_SCL
25	I2C0_SDA
26	DGND
27	VCC_12V0
28	VCC_12V0
29	DGND
30	ENET_EXP_PWRDN
31	QSGMII_INTN
32	DGND
33	QSGMII4_TX_P
34	QSGMII4_TX_N
35	DGND
36	QSGMII4_RX_P

**Table 4-30. ENET Expansion Connector J10 Pinout (continued)**

ENET Expansion Connector Interface J10	
Pin No.	Signal
37	QSGMII4_RX_N
38	DGND
39	QSGMII_PHY_REFCLK_N
40	QSGMII_PHY_REFCLK_P
41	DGND
42	QSGMII_MDC
43	QSGMII_MDIO
44	DGND
45	QSGMII_RESETN
46	CDCI_I2C_SEL
47	ENET_EXP_SPARE
48	DGND
49	VSYS_5V0
50	VSYS_5V0
51	DGND
52	NC
53	NC
54	DGND
55	VCC_3V3
56	VCC_3V3
57	DGND
58	NC
59	NC
60	DGND
SH1	DGND
SH2	DGND

#### 4.22.4 Ethernet Interface

The J7200 EVM includes SGMII connection between VSC8514XMK Quad Port SGMII PHY and the network subsystem (NSS) of the Processor. One channel of SGMII interface (connected to stacked RJ45 connector J1A and J1B, J2A and J2B) from the SERDES0 (SGMII1) domain of J7200 processor are used.

##### 4.22.4.1 Quad Port SGMII PHY Default Configuration

The J7200 EVM uses the 138-pin QFN package, designated with the XMK suffix, which supports only SGMII interface.

The VC8514 device includes three external PHY address pins, PHYADD [4:2] to allow control of multiple PHY devices on a system board sharing a common management bus. These pins set the most significant bits of the PHY address port map. The lower two bits of the address for each port are derived from the physical address of the port (0 to 3) and the setting of the PHY address reversal bit in register 20E1, bit 9

#### 4.22.5 Board ID EEPROM Interface

The Quad port Ethernet Expansion Board is identified by its version and serial number, which are stored in the onboard EEPROM. The EEPROM is accessible on the address 0x54 .

The first 259 bytes of addressable EEPROM memory are preprogrammed with identification information for each board. The remaining 32509 bytes are available to the user for data or code storage.

## 5 Functional Safety

The J7200 EVM design supports many functional safety features, including features for both ASIL-B and ASIL-D levels of safety. However – the EVM does not have any functional safety certification. It is tool to be used for software development and exercising features supported by several of its devices.

For additional information, see the [Powering DRA821 with TPS6594-Q1 and LP8764-Q1 User's Guide](#).

## 6 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision * (October 2020) to Revision A (February 2022)</b>	<b>Page</b>
• Updated the numbering format for tables, figures and cross-references throughout the document.....	4
• Added new <a href="#">Section 1.4</a> .....	5
• Update was made in <a href="#">Section 3.5</a> .....	18

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